

Functional Description

Cyclone[®] II devices contain a two-dimensional row- and column-based architecture to implement custom logic. Column and row interconnects of varying speeds provide signal interconnects between logic array blocks (LABs), embedded memory blocks, and embedded multipliers.

The logic array consists of LABs, with 16 logic elements (LEs) in each LAB. An LE is a small unit of logic providing efficient implementation of user logic functions. LABs are grouped into rows and columns across the device. Cyclone II devices range in density from 4,608 to 68,416 LEs.

Cyclone II devices provide a global clock network and up to four phase-locked loops (PLLs). The global clock network consists of up to 16 global clock lines that drive throughout the entire device. The global clock network can provide clocks for all resources within the device, such as input/output elements (IOEs), LEs, embedded multipliers, and embedded memory blocks. The global clock lines can also be used for other high fan-out signals. Cyclone II PLLs provide general-purpose clocking with clock synthesis and phase shifting as well as external outputs for high-speed differential I/O support.

M4K memory blocks are true dual-port memory blocks with 4K bits of memory plus parity (4,608 bits). These blocks provide dedicated true dual-port, simple dual-port, or single-port memory up to 36-bits wide at up to 260 MHz. These blocks are arranged in columns across the device in between certain LABs. Cyclone II devices offer between 119 to 1,152 Kbits of embedded memory.

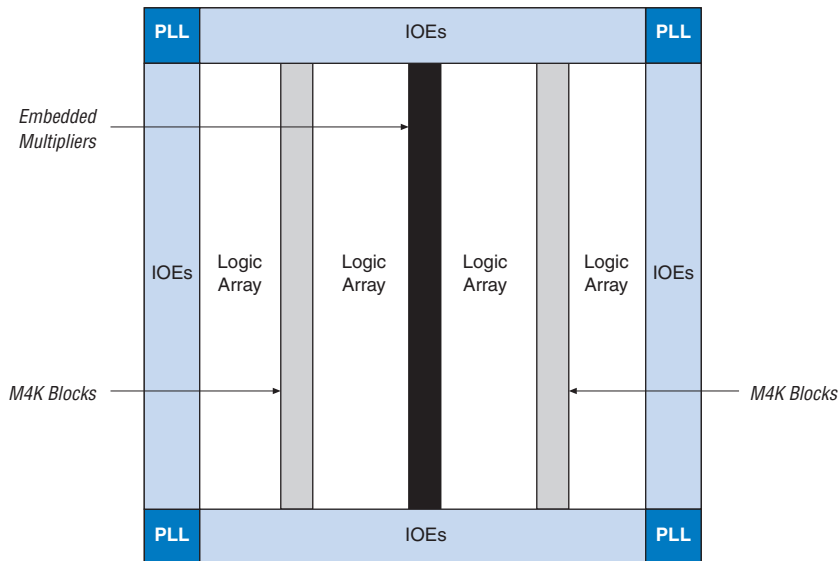
Each embedded multiplier block can implement up to either two 9×9 -bit multipliers, or one 18×18 -bit multiplier with up to 250-MHz performance. Embedded multipliers are arranged in columns across the device.

Each Cyclone II device I/O pin is fed by an IOE located at the ends of LAB rows and columns around the periphery of the device. I/O pins support various single-ended and differential I/O standards, such as the 66- and 33-MHz, 64- and 32-bit PCI standard, PCI-X, and the LVDS I/O standard at a maximum data rate of 805 megabits per second (Mbps) for inputs and 640 Mbps for outputs. Each IOE contains a bidirectional I/O buffer and three registers for registering input, output, and output-enable signals. Dual-purpose DQS, DQ, and DM pins along with delay chains (used to

phase-align double data rate (DDR) signals) provide interface support for external memory devices such as DDR, DDR2, and single data rate (SDR) SDRAM, and QDR II SRAM devices at up to 167 MHz.

Figure 2–1 shows a diagram of the Cyclone II EP2C20 device.

Figure 2–1. Cyclone II EP2C20 Device Block Diagram



The number of M4K memory blocks, embedded multiplier blocks, PLLs, rows, and columns vary per device.

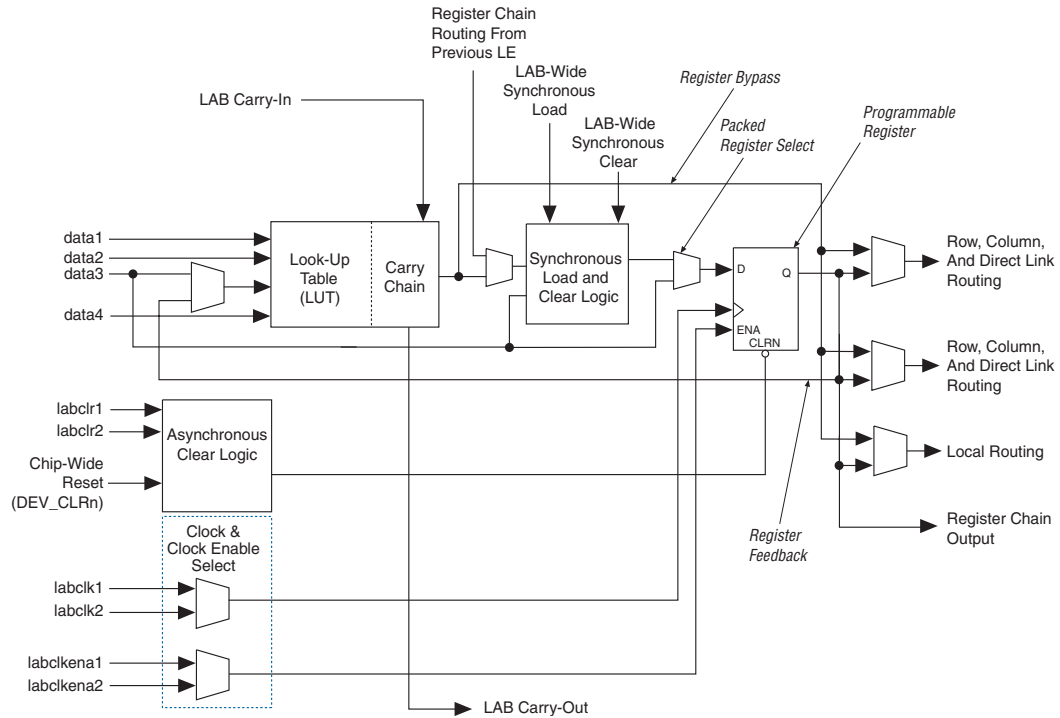
Logic Elements

The smallest unit of logic in the Cyclone II architecture, the LE, is compact and provides advanced features with efficient logic utilization. Each LE features:

- A four-input look-up table (LUT), which is a function generator that can implement any function of four variables
- A programmable register
- A carry chain connection
- A register chain connection
- The ability to drive all types of interconnects: local, row, column, register chain, and direct link interconnects
- Support for register packing
- Support for register feedback

Figure 2–2 shows a Cyclone II LE.

Figure 2–2. Cyclone II LE



Each LE's programmable register can be configured for D, T, JK, or SR operation. Each register has data, clock, clock enable, and clear inputs. Signals that use the global clock network, general-purpose I/O pins, or any internal logic can drive the register's clock and clear control signals. Either general-purpose I/O pins or internal logic can drive the clock enable. For combinational functions, the LUT output bypasses the register and drives directly to the LE outputs.

Each LE has three outputs that drive the local, row, and column routing resources. The LUT or register output can drive these three outputs independently. Two LE outputs drive column or row and direct link routing connections and one drives local interconnect resources, allowing the LUT to drive one output while the register drives another output. This feature, register packing, improves device utilization because the device can use the register and the LUT for unrelated functions. When using register packing, the LAB-wide synchronous load control signal is not available. See "LAB Control Signals" on page 2–8 for more information.

Another special packing mode allows the register output to feed back into the LUT of the same LE so that the register is packed with its own fan-out LUT, providing another mechanism for improved fitting. The LE can also drive out registered and unregistered versions of the LUT output.

In addition to the three general routing outputs, the LEs within an LAB have register chain outputs. Register chain outputs allow registers within the same LAB to cascade together. The register chain output allows an LAB to use LUTs for a single combinational function and the registers to be used for an unrelated shift register implementation. These resources speed up connections between LABs while saving local interconnect resources. See “[MultiTrack Interconnect](#)” on page 2–10 for more information on register chain connections.

LE Operating Modes

The Cyclone II LE operates in one of the following modes:

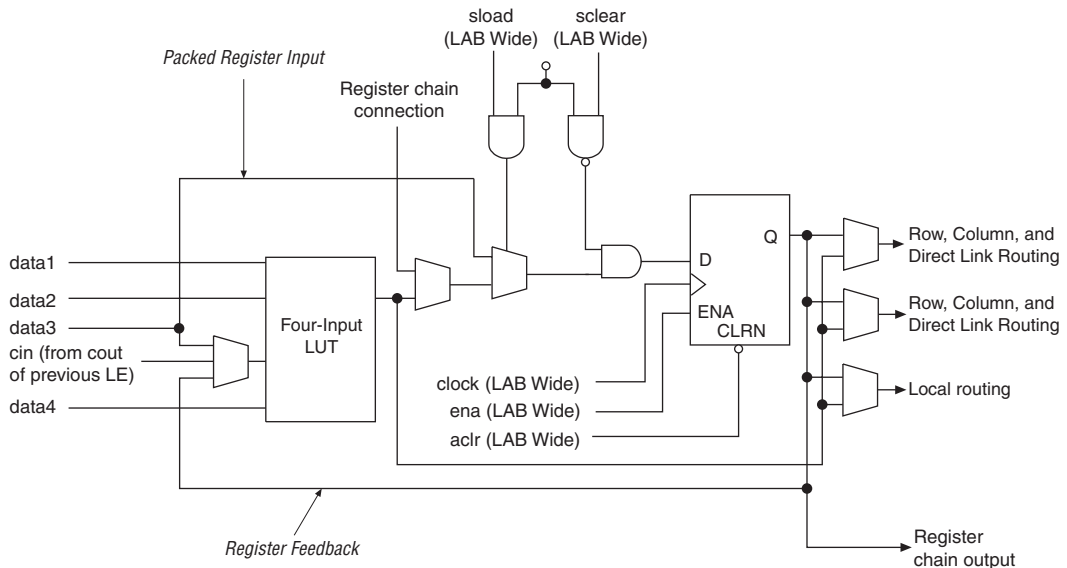
- Normal mode
- Arithmetic mode

Each mode uses LE resources differently. In each mode, six available inputs to the LE—the four data inputs from the LAB local interconnect, the LAB carry-in from the previous carry-chain LAB, and the register chain connection—are directed to different destinations to implement the desired logic function. LAB-wide signals provide clock, asynchronous clear, synchronous clear, synchronous load, and clock enable control for the register. These LAB-wide signals are available in all LE modes.

The Quartus® II software, in conjunction with parameterized functions such as library of parameterized modules (LPM) functions, automatically chooses the appropriate mode for common functions such as counters, adders, subtractors, and arithmetic functions. If required, you can also create special-purpose functions that specify which LE operating mode to use for optimal performance.

Normal Mode

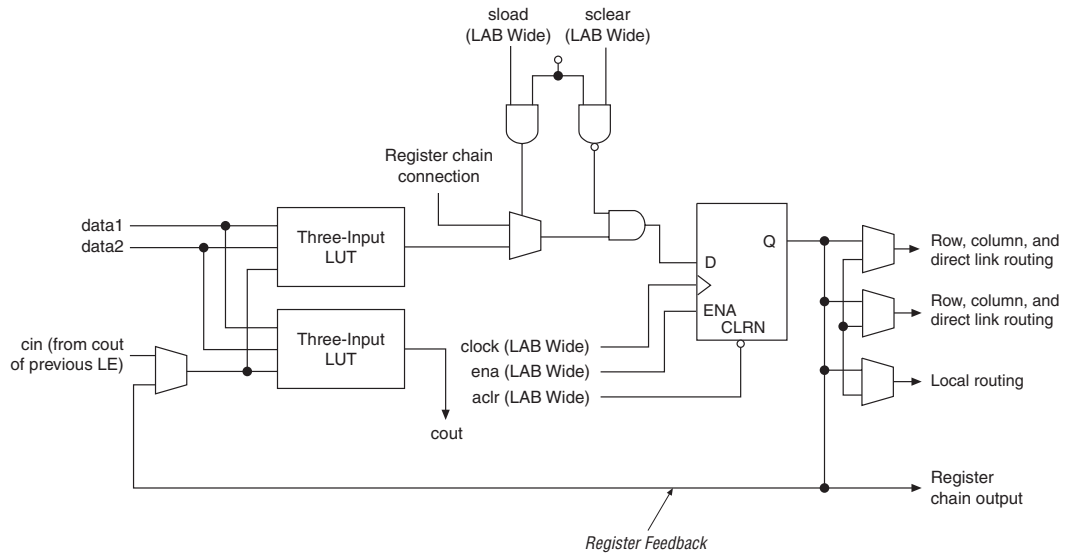
The normal mode is suitable for general logic applications and combinational functions. In normal mode, four data inputs from the LAB local interconnect are inputs to a four-input LUT (see [Figure 2–3](#)). The Quartus II Compiler automatically selects the carry-in or the `data3` signal as one of the inputs to the LUT. LEs in normal mode support packed registers and register feedback.

Figure 2-3. LE in Normal Mode

Arithmetic Mode

The arithmetic mode is ideal for implementing adders, counters, accumulators, and comparators. An LE in arithmetic mode implements a 2-bit full adder and basic carry chain (see [Figure 2-4](#)). LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output. Register feedback and register packing are supported when LEs are used in arithmetic mode.

Figure 2–4. LE in Arithmetic Mode



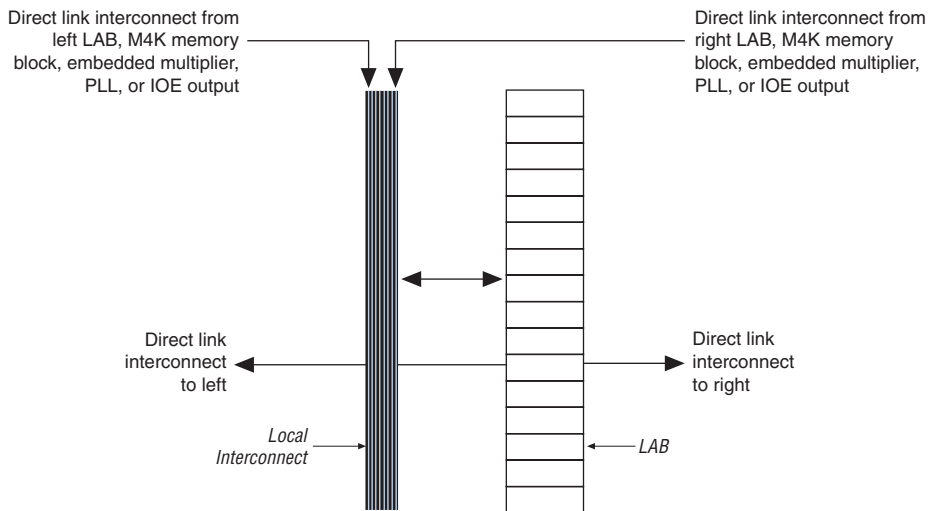
The Quartus II Compiler automatically creates carry chain logic during design processing, or you can create it manually during design entry. Parameterized functions such as LPM functions automatically take advantage of carry chains for the appropriate functions.

The Quartus II Compiler creates carry chains longer than 16 LEs by automatically linking LABs in the same column. For enhanced fitting, a long carry chain runs vertically, which allows fast horizontal connections to M4K memory blocks or embedded multipliers through direct link interconnects. For example, if a design has a long carry chain in a LAB column next to a column of M4K memory blocks, any LE output can feed an adjacent M4K memory block through the direct link interconnect. Whereas if the carry chains ran horizontally, any LAB not next to the column of M4K memory blocks would use other row or column interconnects to drive a M4K memory block. A carry chain continues as far as a full column.

LAB Interconnects

The LAB local interconnect can drive LEs within the same LAB. The LAB local interconnect is driven by column and row interconnects and LE outputs within the same LAB. Neighboring LABs, PLLs, M4K RAM blocks, and embedded multipliers from the left and right can also drive an LAB's local interconnect through the direct link connection. The direct link connection feature minimizes the use of row and column interconnects, providing higher performance and flexibility. Each LE can drive 48 LEs through fast local and direct link interconnects. Figure 2-6 shows the direct link connection.

Figure 2-6. Direct Link Connection



LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include:

- Two clocks
- Two clock enables
- Two asynchronous clears
- One synchronous clear
- One synchronous load

This gives a maximum of seven control signals at a time. When using the LAB-wide synchronous load, the `clkena` of `labclk1` is not available. Additionally, register packing and synchronous load cannot be used simultaneously.

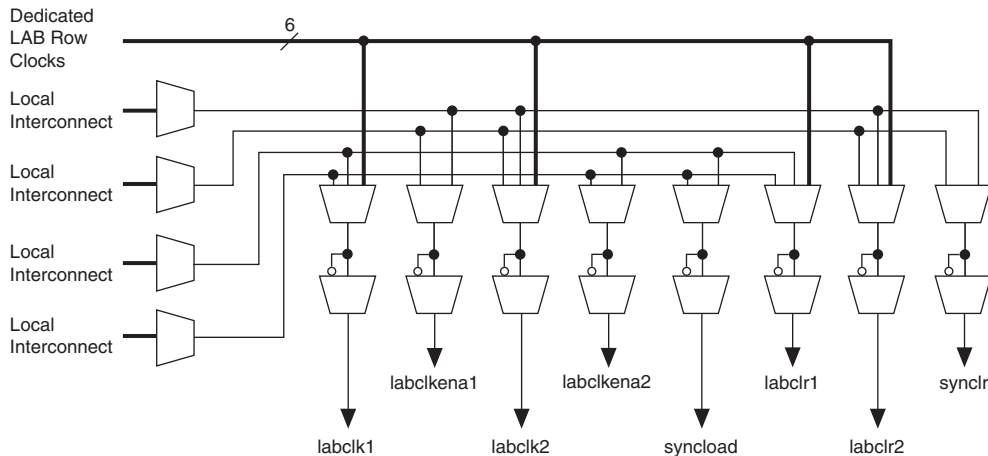
Each LAB can have up to four non-global control signals. Additional LAB control signals can be used as long as they are global signals.

Synchronous clear and load signals are useful for implementing counters and other functions. The synchronous clear and synchronous load signals are LAB-wide signals that affect all registers in the LAB.

Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked. For example, any LE in a particular LAB using the `labclk1` signal also uses `labckena1`. If the LAB uses both the rising and falling edges of a clock, it also uses both LAB-wide clock signals. De-asserting the clock enable signal turns off the LAB-wide clock.

The LAB row clocks [5..0] and LAB local interconnect generate the LAB-wide control signals. The MultiTrack™ interconnect's inherent low skew allows clock and control signal distribution in addition to data. [Figure 2-7](#) shows the LAB control signal generation circuit.

Figure 2-7. LAB-Wide Control Signals



LAB-wide signals control the logic for the register's clear signal. The LE directly supports an asynchronous clear function. Each LAB supports up to two asynchronous clear signals (`labclr1` and `labclr2`).

A LAB-wide asynchronous load signal to control the logic for the register's preset signal is not available. The register preset is achieved by using a NOT gate push-back technique. Cyclone II devices can only support either a preset or asynchronous clear signal.

In addition to the clear port, Cyclone II devices provide a chip-wide reset pin (`DEV_CLRn`) that resets all registers in the device. An option set before compilation in the Quartus II software controls this pin. This chip-wide reset overrides all other control signals.

MultiTrack Interconnect

In the Cyclone II architecture, connections between LEs, M4K memory blocks, embedded multipliers, and device I/O pins are provided by the MultiTrack interconnect structure with DirectDrive™ technology. The MultiTrack interconnect consists of continuous, performance-optimized routing lines of different speeds used for inter- and intra-design block connectivity. The Quartus II Compiler automatically places critical paths on faster interconnects to improve design performance.

DirectDrive technology is a deterministic routing technology that ensures identical routing resource usage for any function regardless of placement within the device. The MultiTrack interconnect and DirectDrive technology simplify the integration stage of block-based designing by eliminating the re-optimization cycles that typically follow design changes and additions.

The MultiTrack interconnect consists of row (direct link, R4, and R24) and column (register chain, C4, and C16) interconnects that span fixed distances. A routing structure with fixed-length resources for all devices allows predictable and repeatable performance when migrating through different device densities.

Row Interconnects

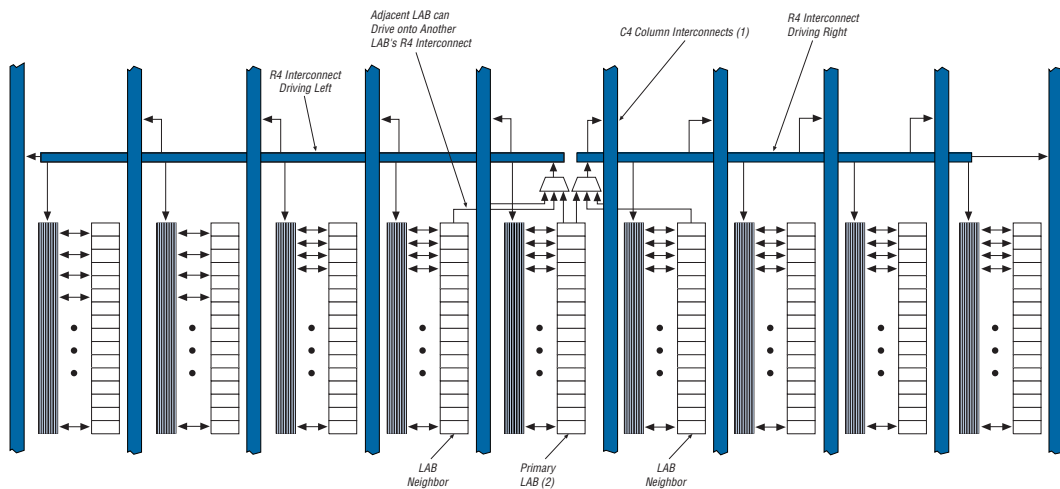
Dedicated row interconnects route signals to and from LABs, PLLs, M4K memory blocks, and embedded multipliers within the same row. These row resources include:

- Direct link interconnects between LABs and adjacent blocks
- R4 interconnects traversing four blocks to the right or left
- R24 interconnects for high-speed access across the length of the device

The direct link interconnect allows an LAB, M4K memory block, or embedded multiplier block to drive into the local interconnect of its left and right neighbors. Only one side of a PLL block interfaces with direct link and row interconnects. The direct link interconnect provides fast communication between adjacent LABs and/or blocks without using row interconnect resources.

The R4 interconnects span four LABs, three LABs and one M4K memory block, or three LABs and one embedded multiplier to the right or left of a source LAB. These resources are used for fast row connections in a four-LAB region. Every LAB has its own set of R4 interconnects to drive either left or right. [Figure 2–8](#) shows R4 interconnect connections from an LAB. R4 interconnects can drive and be driven by LABs, M4K memory blocks, embedded multipliers, PLLs, and row IOEs. For LAB interfacing, a primary LAB or LAB neighbor (see [Figure 2–8](#)) can drive a given R4 interconnect. For R4 interconnects that drive to the right, the primary LAB and right neighbor can drive on to the interconnect. For R4 interconnects that drive to the left, the primary LAB and its left neighbor can drive on to the interconnect. R4 interconnects can drive other R4 interconnects to extend the range of LABs they can drive. Additionally, R4 interconnects can drive R24 interconnects, C4, and C16 interconnects for connections from one row to another.

Figure 2–8. R4 Interconnect Connections



Notes to [Figure 2–8](#):

- (1) C4 interconnects can drive R4 interconnects.
- (2) This pattern is repeated for every LAB in the LAB row.

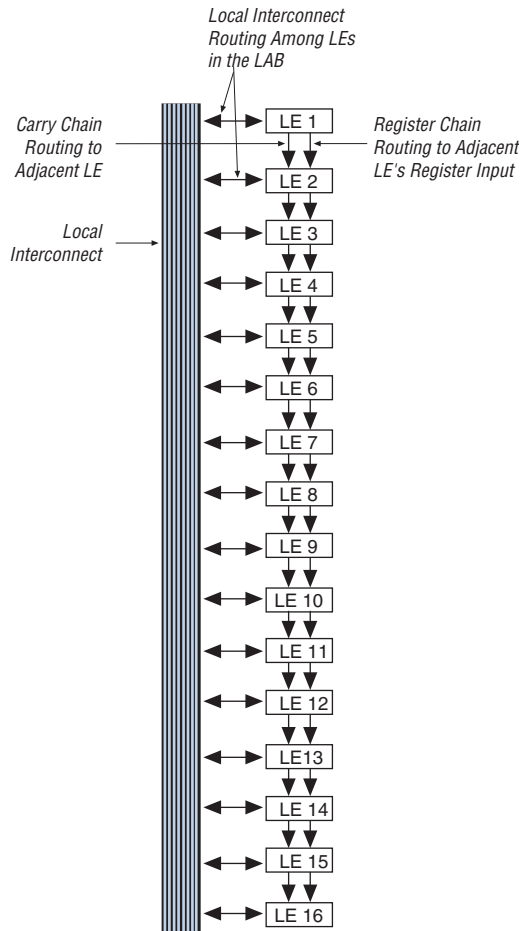
R24 row interconnects span 24 LABs and provide the fastest resource for long row connections between non-adjacent LABs, M4K memory blocks, dedicated multipliers, and row IOEs. R24 row interconnects drive to other row or column interconnects at every fourth LAB. R24 row interconnects drive LAB local interconnects via R4 and C4 interconnects and do not drive directly to LAB local interconnects. R24 interconnects can drive R24, R4, C16, and C4 interconnects.

Column Interconnects

The column interconnect operates similar to the row interconnect. Each column of LABs is served by a dedicated column interconnect, which vertically routes signals to and from LABs, M4K memory blocks, embedded multipliers, and row and column IOEs. These column resources include:

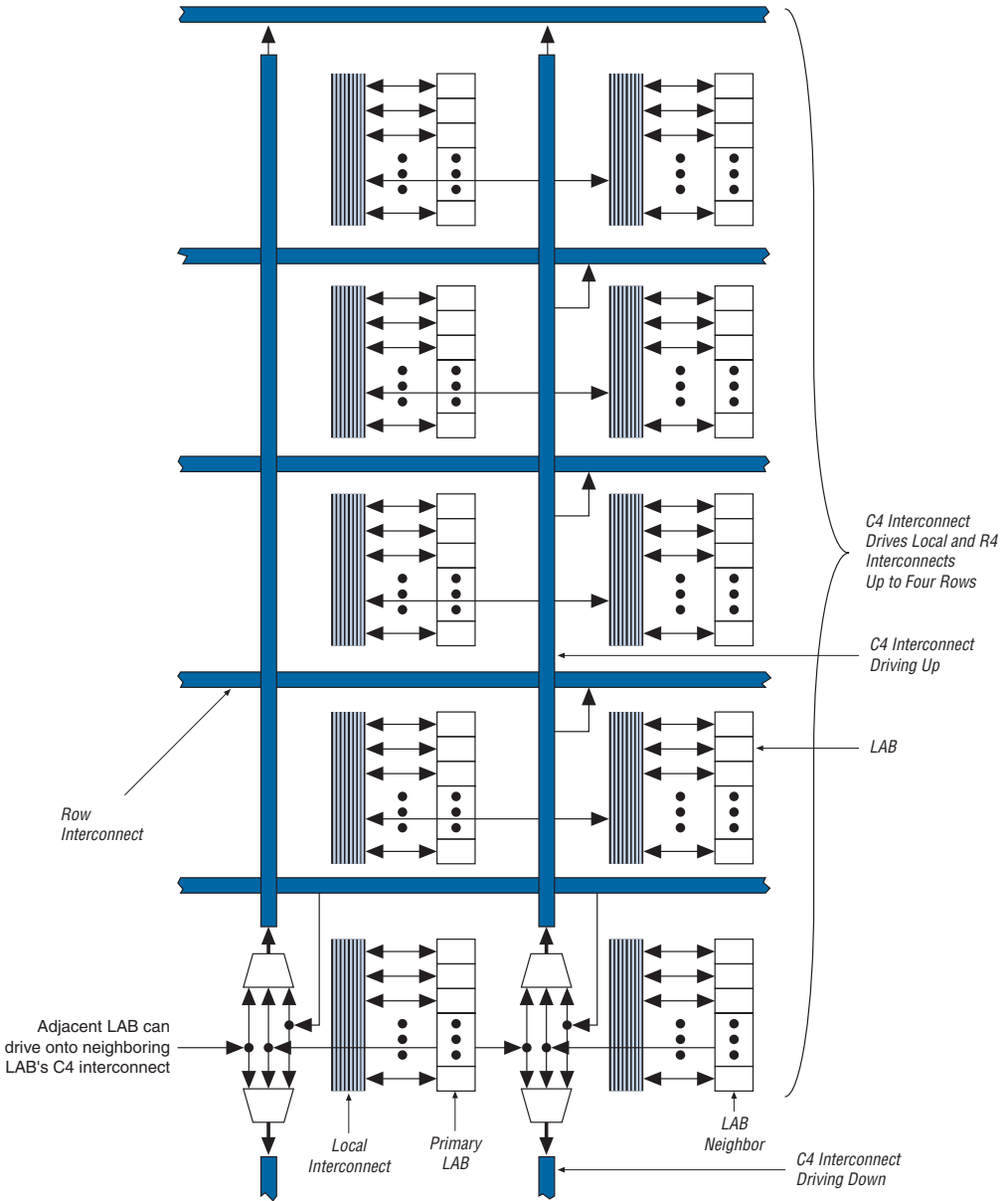
- Register chain interconnects within an LAB
- C4 interconnects traversing a distance of four blocks in an up and down direction
- C16 interconnects for high-speed vertical routing through the device

Cyclone II devices include an enhanced interconnect structure within LABs for routing LE output to LE input connections faster using register chain connections. The register chain connection allows the register output of one LE to connect directly to the register input of the next LE in the LAB for fast shift registers. The Quartus II Compiler automatically takes advantage of these resources to improve utilization and performance. [Figure 2-9](#) shows the register chain interconnects.

Figure 2–9. Register Chain Interconnects

The C4 interconnects span four LABs, M4K blocks, or embedded multipliers up or down from a source LAB. Every LAB has its own set of C4 interconnects to drive either up or down. [Figure 2–10](#) shows the C4 interconnect connections from an LAB in a column. The C4 interconnects can drive and be driven by all types of architecture blocks, including PLLs, M4K memory blocks, embedded multiplier blocks, and column and row IOEs. For LAB interconnection, a primary LAB or its LAB neighbor (see [Figure 2–10](#)) can drive a given C4 interconnect. C4 interconnects can drive each other to extend their range as well as drive row interconnects for column-to-column connections.

Figure 2-10. C4 Interconnect Connections Note (1)



Note to Figure 2-10:

(1) Each C4 interconnect can drive either up or down four rows.

C16 column interconnects span a length of 16 LABs and provide the fastest resource for long column connections between LABs, M4K memory blocks, embedded multipliers, and IOEs. C16 column interconnects drive to other row and column interconnects at every fourth LAB. C16 column interconnects drive LAB local interconnects via C4 and R4 interconnects and do not drive LAB local interconnects directly. C16 interconnects can drive R24, R4, C16, and C4 interconnects.

Device Routing

All embedded blocks communicate with the logic array similar to LAB-to-LAB interfaces. Each block (for example, M4K memory, embedded multiplier, or PLL) connects to row and column interconnects and has local interconnect regions driven by row and column interconnects. These blocks also have direct link interconnects for fast connections to and from a neighboring LAB.

Table 2-1 shows the Cyclone II device's routing scheme.

Table 2-1. Cyclone II Device Routing Scheme (Part 1 of 2)

Source	Destination												
	Register Chain	Local Interconnect	Direct Link Interconnect	R4 Interconnect	R24 Interconnect	C4 Interconnect	C16 Interconnect	LE	M4K RAM Block	Embedded Multiplier	PLL	Column IOE	Row IOE
Register Chain								✓					
Local Interconnect								✓	✓	✓	✓	✓	✓
Direct Link Interconnect		✓											
R4 Interconnect		✓		✓	✓	✓	✓						
R24 Interconnect				✓	✓	✓	✓						
C4 Interconnect		✓		✓	✓	✓	✓						
C16 Interconnect				✓	✓	✓	✓						

Table 2–1. Cyclone II Device Routing Scheme (Part 2 of 2)

Source	Destination												
	Register Chain	Local Interconnect	Direct Link Interconnect	R4 Interconnect	R24 Interconnect	C4 Interconnect	C16 Interconnect	LE	M4K RAM Block	Embedded Multiplier	PLL	Column IOE	Row IOE
LE	✓	✓	✓	✓		✓							
M4K memory Block		✓	✓	✓		✓							
Embedded Multipliers		✓	✓	✓		✓							
PLL			✓	✓		✓							
Column IOE						✓	✓						
Row IOE			✓	✓	✓	✓							

Global Clock Network & Phase-Locked Loops

Cyclone II devices provide global clock networks and up to four PLLs for a complete clock management solution. Cyclone II clock network features include:

- Up to 16 global clock networks
- Up to four PLLs
- Global clock network dynamic clock source selection
- Global clock network dynamic enable and disable

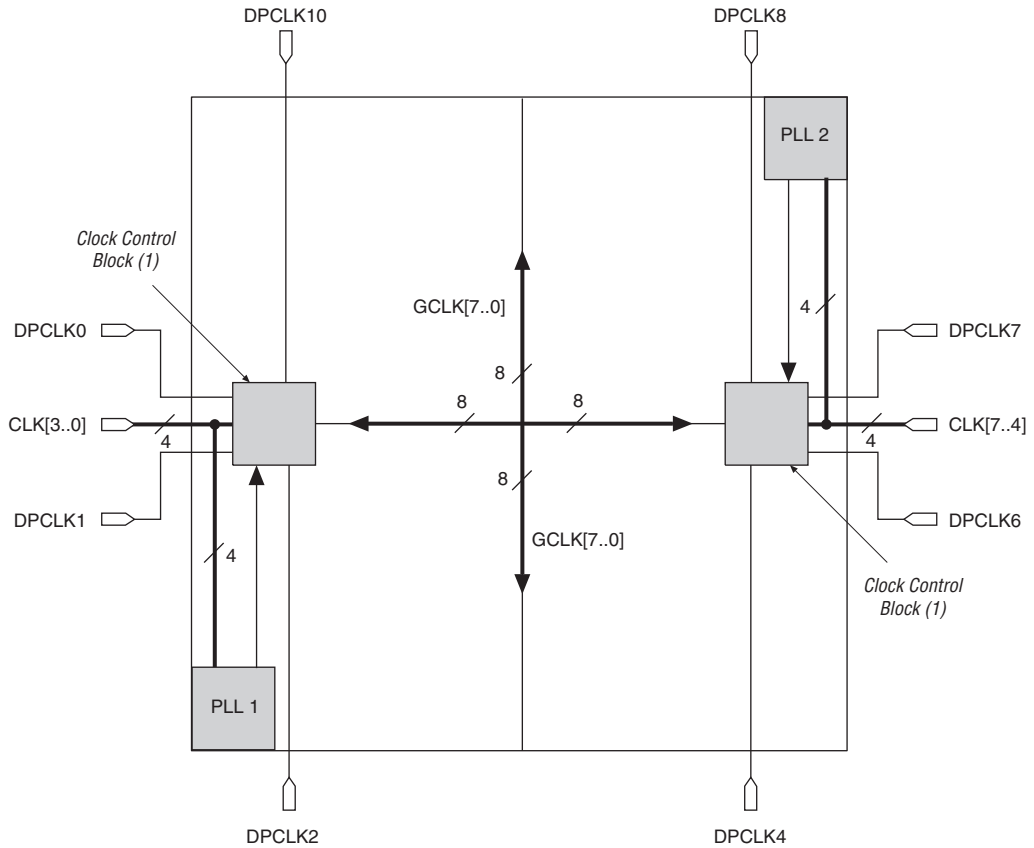
Each global clock network has a clock control block to select from a number of input clock sources (PLL clock outputs, CLK [] pins, DPCLK [] pins, and internal logic) to drive onto the global clock network. Table 2–2 lists how many PLLs, CLK [] pins, DPCLK [] pins, and global clock networks are available in each Cyclone II device. CLK [] pins are dedicated clock pins and DPCLK [] pins are dual-purpose clock pins.

Table 2–2. Cyclone II Device Clock Resources

Device	Number of PLLs	Number of CLK Pins	Number of DPCLK Pins	Number of Global Clock Networks
EP2C5	2	8	8	8
EP2C8	2	8	8	8
EP2C15	4	16	20	16
EP2C20	4	16	20	16
EP2C35	4	16	20	16
EP2C50	4	16	20	16
EP2C70	4	16	20	16

Figures 2–11 and 2–12 show the location of the Cyclone II PLLs, CLK [] inputs, DPCLK [] pins, and clock control blocks.

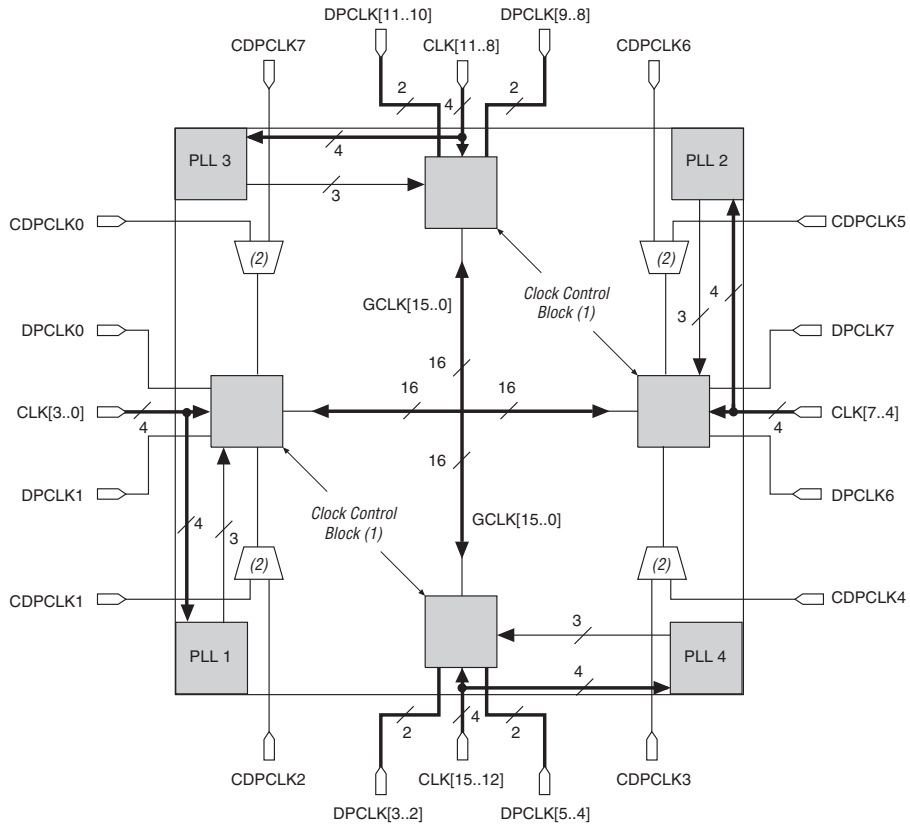
Figure 2-11. EP2C5 & EP2C8 PLL, CLK[], DPCLK[] & Clock Control Block Locations



Note to Figure 2-11:

(1) There are four clock control blocks on each side.

Figure 2–12. EP2C15 & Larger PLL, CLK[], DPCLK[] & Clock Control Block Locations



Notes to Figure 2–12:

- (1) There are four clock control blocks on each side.
- (2) Only one of the corner CDPCLK pins in each corner can feed the clock control block at a time. The other CDPCLK pins can be used as general-purpose I/O pins.

Dedicated Clock Pins

Larger Cyclone II devices (EP2C15 and larger devices) have 16 dedicated clock pins (CLK [15 . . 0], four pins on each side of the device). Smaller Cyclone II devices (EP2C5 and EP2C8 devices) have eight dedicated clock pins (CLK [7 . . 0], four pins on left and right sides of the device). These CLK pins drive the global clock network (GCLK), as shown in [Figures 2–11 and 2–12](#).

If the dedicated clock pins are not used to feed the global clock networks, they can be used as general-purpose input pins to feed the logic array using the MultiTrack interconnect. However, if they are used as general-purpose input pins, they do not have support for an I/O register and must use LE-based registers in place of an I/O register.

Dual-Purpose Clock Pins

Cyclone II devices have either 20 dual-purpose clock pins, DPCLK [19 . . 0] or 8 dual-purpose clock pins, DPCLK [7 . . 0]. In the larger Cyclone II devices (EP2C15 devices and higher), there are 20 DPCLK pins; four on the left and right sides and six on the top and bottom of the device. The corner CDPCLK pins are first multiplexed before they drive into the clock control block. Since the signals pass through a multiplexer before feeding the clock control block, these signals incur more delay to the clock control block than other DPCLK pins that directly feed the clock control block. In the smaller Cyclone II devices (EP2C5 and EP2C8 devices), there are eight DPCLK pins; two on each side of the device (see [Figures 2–11 and 2–12](#)).

A programmable delay chain is available from the DPCLK pin to its fan-out destinations. To set the propagation delay from the DPCLK pin to its fan-out destinations, use the **Input Delay from Dual-Purpose Clock Pin to Fan-Out Destinations** assignment in the Quartus II software.

These dual-purpose pins can connect to the global clock network for high-fanout control signals such as clocks, asynchronous clears, presets, and clock enables, or protocol control signals such as TRDY and IRDY for PCI, or DQS signals for external memory interfaces.

Global Clock Network

The 16 or 8 global clock networks drive throughout the entire device. Dedicated clock pins (CLK []), PLL outputs, the logic array, and dual-purpose clock (DPCLK []) pins can also drive the global clock network.

The global clock network can provide clocks for all resources within the device, such as IOEs, LEs, memory blocks, and embedded multipliers. The global clock lines can also be used for control signals, such as clock enables and synchronous or asynchronous clears fed from the external pin, or DQS signals for DDR SDRAM or QDR II SRAM interfaces. Internal logic can also drive the global clock network for internally generated global clocks and asynchronous clears, clock enables, or other control signals with large fan-out.

Clock Control Block

There is a clock control block for each global clock network available in Cyclone II devices. The clock control blocks are arranged on the device periphery and there are a maximum of 16 clock control blocks available per Cyclone II device. The larger Cyclone II devices (EP2C15 devices and larger) have 16 clock control blocks, four on each side of the device. The smaller Cyclone II devices (EP2C5 and EP2C8 devices) have eight clock control blocks, four on the left and right sides of the device.

The control block has these functions:

- Dynamic global clock network clock source selection
- Dynamic enable/disable of the global clock network

In Cyclone II devices, the dedicated CLK [] pins, PLL counter outputs, DPCLK [] pins, and internal logic can all feed the clock control block. The output from the clock control block in turn feeds the corresponding global clock network.

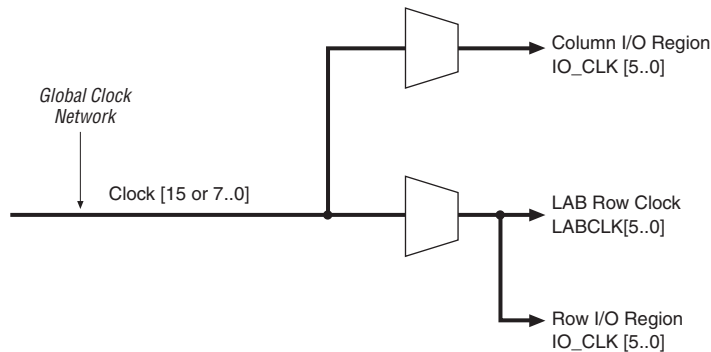
The following sources can be inputs to a given clock control block:

- Four clock pins on the same side as the clock control block
- Three PLL clock outputs from a PLL
- Four DPCLK pins (including CDPCLK pins) on the same side as the clock control block
- Four internally-generated signals

Global Clock Network Distribution

Cyclone II devices contains 16 global clock networks. The device uses multiplexers with these clocks to form six-bit buses to drive column IOE clocks, LAB row clocks, or row IOE clocks (see [Figure 2-14](#)). Another multiplexer at the LAB level selects two of the six LAB row clocks to feed the LE registers within the LAB.

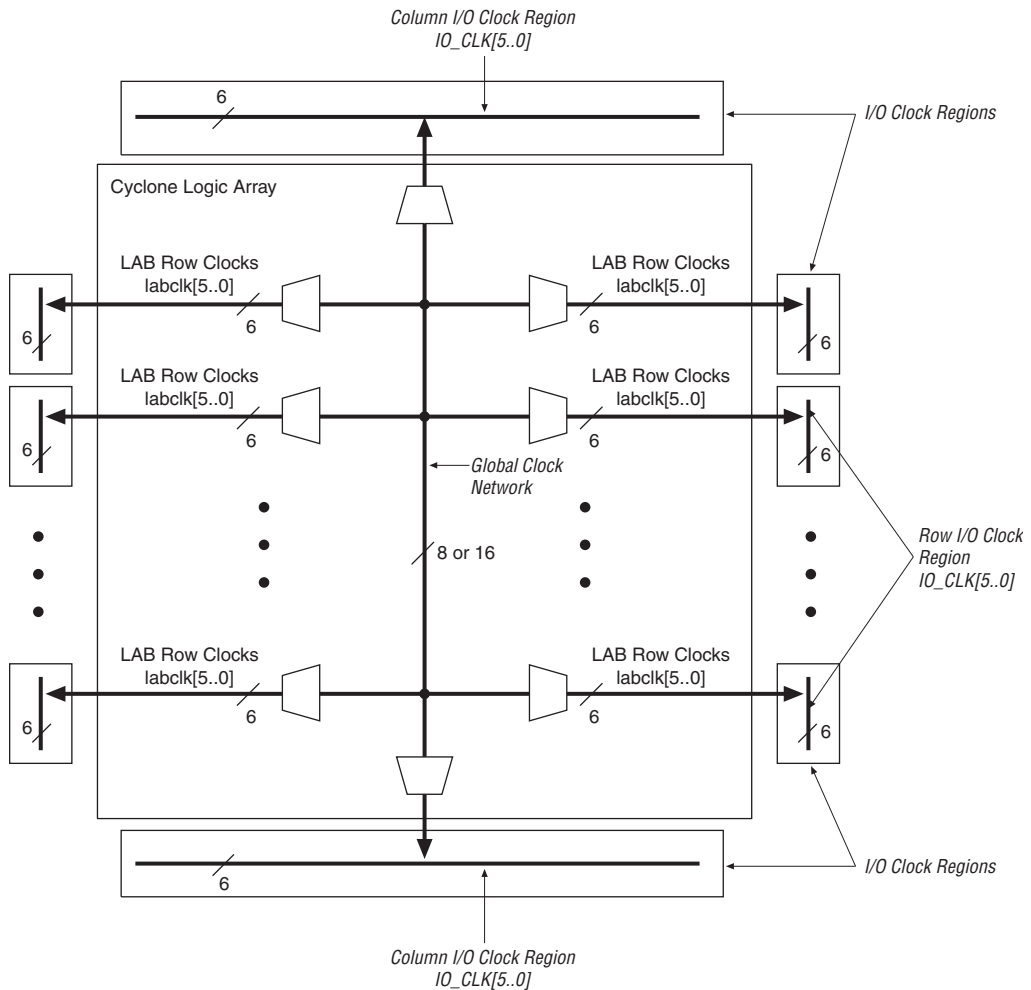
Figure 2-14. Global Clock Network Multiplexers



LAB row clocks can feed LEs, M4K memory blocks, and embedded multipliers. The LAB row clocks also extend to the row I/O clock regions.

IOE clocks are associated with row or column block regions. Only six global clock resources feed to these row and column regions. [Figure 2-15](#) shows the I/O clock regions.

Figure 2-15. LAB & I/O Clock Regions



For more information on the global clock network and the clock control block, see the *PLLs in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

PLLs

Cyclone II PLLs provide general-purpose clocking as well as support for the following features:

- Clock multiplication and division
- Phase shifting
- Programmable duty cycle
- Up to three internal clock outputs
- One dedicated external clock output
- Clock outputs for differential I/O support
- Manual clock switchover
- Gated lock signal
- Three different clock feedback modes
- Control signals

Cyclone II devices contain either two or four PLLs. [Table 2-3](#) shows the PLLs available for each Cyclone II device.

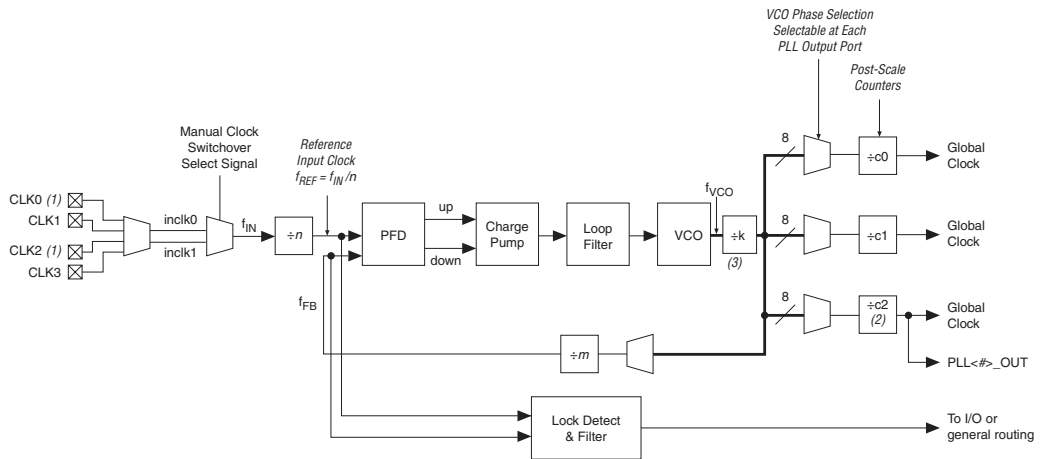
Device	PLL1	PLL2	PLL3	PLL4
EP2C5	✓	✓		
EP2C8	✓	✓		
EP2C15	✓	✓	✓	✓
EP2C20	✓	✓	✓	✓
EP2C35	✓	✓	✓	✓
EP2C50	✓	✓	✓	✓
EP2C70	✓	✓	✓	✓

Table 2–4 describes the PLL features in Cyclone II devices.

Table 2–4. Cyclone II PLL Features	
Feature	Description
Clock multiplication and division	$m / (n \times \text{post-scale counter})$ m and post-scale counter values (C0 to C2) range from 1 to 32. n ranges from 1 to 4.
Phase shift	Cyclone II PLLs have an advanced clock shift capability that enables programmable phase shifts in increments of at least 45°. The finest resolution of phase shifting is determined by the voltage control oscillator (VCO) period divided by 8 (for example, 1/1000 MHz/8 = down to 125-ps increments).
Programmable duty cycle	The programmable duty cycle allows PLLs to generate clock outputs with a variable duty cycle. This feature is supported on each PLL post-scale counter (C0-C2).
Number of internal clock outputs	The Cyclone II PLL has three outputs which can drive the global clock network. One of these outputs (C2) can also drive a dedicated PLL<#>_OUT pin (single ended or differential).
Number of external clock outputs	The C2 output drives a dedicated PLL<#>_OUT pin. If the C2 output is not used to drive an external clock output, it can be used to drive the internal global clock network. The C2 output can concurrently drive the external clock output and internal global clock network.
Manual clock switchover	The Cyclone II PLLs support manual switchover of the reference clock through internal logic. This enables you to switch between two reference input clocks during user mode for applications that may require clock redundancy or support for clocks with two different frequencies.
Gated lock signal	The lock output indicates that there is a stable clock output signal in phase with the reference clock. Cyclone II PLLs include a programmable counter that holds the lock signal low for a user-selected number of input clock transitions, allowing the PLL to lock before enabling the locked signal. Either a gated locked signal or an ungated locked signal from the locked port can drive internal logic or an output pin.
Clock feedback modes	In zero delay buffer mode, the external clock output pin is phase-aligned with the clock input pin for zero delay. In normal mode, the PLL compensates for the internal global clock network delay from the input clock pin to the clock port of the IOE output registers or registers in the logic array. In no compensation mode, the PLL does not compensate for any clock networks.
Control signals	The <code>pllenable</code> signal enables and disables the PLLs. The <code>areset</code> signal resets/resynchronizes the inputs for each PLL. The <code>pfdena</code> signal controls the phase frequency detector (PFD) output with a programmable gate.

Figure 2–16 shows a block diagram of the Cyclone II PLL.

Figure 2–16. Cyclone II PLL *Note (1)*



Notes to Figure 2–16:

- (1) This input can be single-ended or differential. If you are using a differential I/O standard, then two CLK pins are used. LVDS input is supported via the secondary function of the dedicated CLK pins. For example, the CLK0 pin's secondary function is LVDSCLK1p and the CLK1 pin's secondary function is LVDSCLK1n. If a differential I/O standard is assigned to the PLL clock input pin, the corresponding CLK (n) pin is also completely used. The Figure 2–16 shows the possible clock input connections (CLK0/CLK1) to PLL1.
- (2) This counter output is shared between a dedicated external clock output I/O and the global clock network.



For more information on Cyclone II PLLs, see the PLLs in the *Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Embedded Memory

The Cyclone II embedded memory consists of columns of M4K memory blocks. The M4K memory blocks include input registers that synchronize writes and output registers to pipeline designs and improve system performance. The output registers can be bypassed, but input registers cannot.

Each M4K block can implement various types of memory with or without parity, including true dual-port, simple dual-port, and single-port RAM, ROM, and first-in first-out (FIFO) buffers. The M4K blocks support the following features:

- 4,608 RAM bits
- 250-MHz performance
- True dual-port memory
- Simple dual-port memory
- Single-port memory
- Byte enable
- Parity bits
- Shift register
- FIFO buffer
- ROM
- Various clock modes
- Address clock enable



Violating the setup or hold time on the memory block address registers could corrupt memory contents. This applies to both read and write operations.

Table 2-5 shows the capacity and distribution of the M4K memory blocks in each Cyclone II device.

Device	M4K Columns	M4K Blocks	Total RAM Bits
EP2C5	2	26	119,808
EP2C8	2	36	165,888
EP2C15	2	52	239,616
EP2C20	2	52	239,616
EP2C35	3	105	483,840
EP2C50	3	129	594,432
EP2C70	5	250	1,152,000

Table 2–6 summarizes the features supported by the M4K memory.

Table 2–6. M4K Memory Features	
Feature	Description
Maximum performance (1)	250 MHz
Total RAM bits per M4K block (including parity bits)	4,608
Configurations supported	4K × 1 2K × 2 1K × 4 512 × 8 512 × 9 256 × 16 256 × 18 128 × 32 (not available in true dual-port mode) 128 × 36 (not available in true dual-port mode)
Parity bits	One parity bit for each byte. The parity bit, along with internal user logic, can implement parity checking for error detection to ensure data integrity.
Byte enable	M4K blocks support byte writes when the write port has a data width of 1, 2, 4, 8, 9, 16, 18, 32, or 36 bits. The byte enables allow the input data to be masked so the device can write to specific bytes. The unwritten bytes retain the previous written value.
Packed mode	Two single-port memory blocks can be packed into a single M4K block if each of the two independent block sizes are equal to or less than half of the M4K block size, and each of the single-port memory blocks is configured in single-clock mode.
Address clock enable	M4K blocks support address clock enable, which is used to hold the previous address value for as long as the signal is enabled. This feature is useful in handling misses in cache applications.
Memory initialization file (.mif)	When configured as RAM or ROM, you can use an initialization file to pre-load the memory contents.
Power-up condition	Outputs cleared
Register clears	Output registers only
Same-port read-during-write	New data available at positive clock edge
Mixed-port read-during-write	Old data available at positive clock edge

Note to Table 2–6:

(1) Maximum performance information is preliminary until device characterization.

Memory Modes

Table 2–7 summarizes the different memory modes supported by the M4K memory blocks.

<i>Table 2–7. M4K Memory Modes</i>	
Memory Mode	Description
Single-port memory	M4K blocks support single-port mode, used when simultaneous reads and writes are not required. Single-port memory supports non-simultaneous reads and writes.
Simple dual-port memory	Simple dual-port memory supports a simultaneous read and write.
Simple dual-port with mixed width	Simple dual-port memory mode with different read and write port widths.
True dual-port memory	True dual-port mode supports any combination of two-port operations: two reads, two writes, or one read and one write at two different clock frequencies.
True dual-port with mixed width	True dual-port mode with different read and write port widths.
Embedded shift register	M4K memory blocks are used to implement shift registers. Data is written into each address location at the falling edge of the clock and read from the address at the rising edge of the clock.
ROM	The M4K memory blocks support ROM mode. A MIF initializes the ROM contents of these blocks.
FIFO buffers	A single clock or dual clock FIFO may be implemented in the M4K blocks. Simultaneous read and write from an empty FIFO buffer is not supported.



Embedded Memory can be inferred in your HDL code or directly instantiated in the Quartus II software using the MegaWizard® Plug-in Manager Memory Compiler feature.

Clock Modes

Table 2–8 summarizes the different clock modes supported by the M4K memory.

Clock Mode	Description
Independent	In this mode, a separate clock is available for each port (ports A and B). Clock A controls all registers on the port A side, while clock B controls all registers on the port B side.
Input/output	On each of the two ports, A or B, one clock controls all registers for inputs into the memory block: data input, <i>wren</i> , and address. The other clock controls the block's data output registers.
Read/write	Up to two clocks are available in this mode. The write clock controls the block's data inputs, <i>wraddress</i> , and <i>wren</i> . The read clock controls the data output, <i>rdaddress</i> , and <i>rden</i> .
Single	In this mode, a single clock, together with clock enable, is used to control all registers of the memory block. Asynchronous clear signals for the registers are not supported.

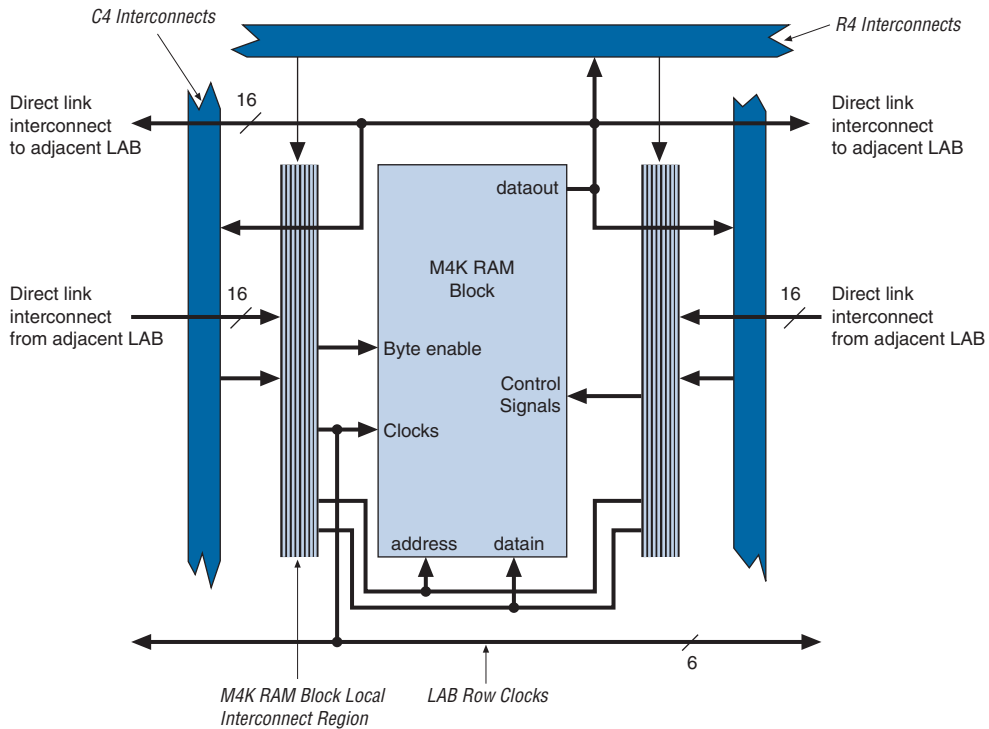
Table 2–9 shows which clock modes are supported by all M4K blocks when configured in the different memory modes.

Clocking Modes	True Dual-Port Mode	Simple Dual-Port Mode	Single-Port Mode
Independent	✓		
Input/output	✓	✓	✓
Read/write		✓	
Single clock	✓	✓	✓

M4K Routing Interface

The R4, C4, and direct link interconnects from adjacent LABs drive the M4K block local interconnect. The M4K blocks can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 16 direct link input connections to the M4K block are possible from the left adjacent LAB and another 16 possible from the right adjacent LAB. M4K block outputs can also connect to left and right LABs through each 16 direct link interconnects. Figure 2–17 shows the M4K block to logic array interface.

Figure 2-17. M4K RAM Block LAB Row Interface



For more information on Cyclone II embedded memory, see the *Cyclone II Memory Blocks* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Embedded Multipliers

Cyclone II devices have embedded multiplier blocks optimized for multiplier-intensive digital signal processing (DSP) functions, such as finite impulse response (FIR) filters, fast Fourier transform (FFT) functions, and discrete cosine transform (DCT) functions. You can use the embedded multiplier in one of two basic operational modes, depending on the application needs:

- One 18-bit multiplier
- Up to two independent 9-bit multipliers

Embedded multipliers can operate at up to 250 MHz (for the fastest speed grade) for 18×18 and 9×9 multiplications when using both input and output registers.

Each Cyclone II device has one to three columns of embedded multipliers that efficiently implement multiplication functions. An embedded multiplier spans the height of one LAB row. Table 2–10 shows the number of embedded multipliers in each Cyclone II device and the multipliers that can be implemented.

Device	Embedded Multiplier Columns	Embedded Multipliers	9×9 Multipliers	18×18 Multipliers
EP2C5	1	13	26	13
EP2C8	1	18	36	18
EP2C15	1	26	52	26
EP2C20	1	26	52	26
EP2C35	1	35	70	35
EP2C50	2	86	172	86
EP2C70	3	150	300	150

Note to Table 2–10:

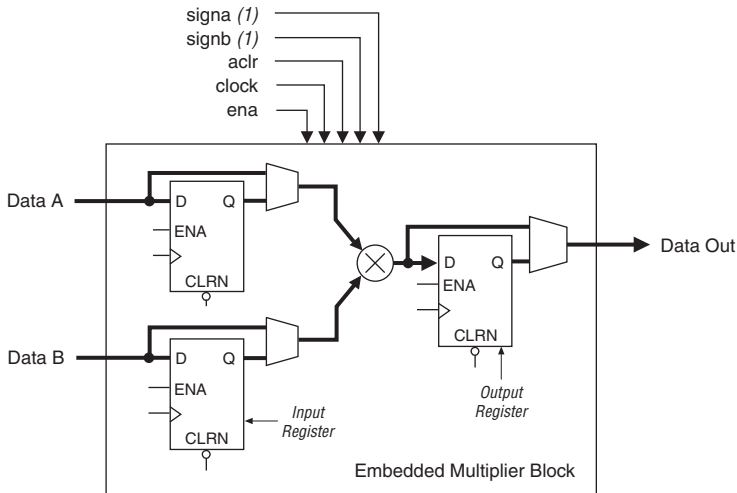
- (1) Each device has either the number of 9×9 -, or 18×18 -bit multipliers shown. The total number of multipliers for each device is not the sum of all the multipliers.

The embedded multiplier consists of the following elements:

- Multiplier block
- Input and output registers
- Input and output interfaces

Figure 2–18 shows the multiplier block architecture.

Figure 2–18. Multiplier Block Architecture



Note to Figure 2–18:

(1) If necessary, these signals can be registered once to match the data signal path.

Each multiplier operand can be a unique signed or unsigned number. Two signals, *signa* and *signb*, control the representation of each operand respectively. A logic 1 value on the *signa* signal indicates that data A is a signed number while a logic 0 value indicates an unsigned number. Table 2–11 shows the sign of the multiplication result for the various operand sign representations. The result of the multiplication is signed if any one of the operands is a signed value.

Data A (signa Value)	Data B (signb Value)	Result
Unsigned	Unsigned	Unsigned
Unsigned	Signed	Signed
Signed	Unsigned	Signed
Signed	Signed	Signed

There is only one `signa` and one `signb` signal for each dedicated multiplier. Therefore, all of the data A inputs feeding the same dedicated multiplier must have the same sign representation. Similarly, all of the data B inputs feeding the same dedicated multiplier must have the same sign representation. The `signa` and `signb` signals can be changed dynamically to modify the sign representation of the input operands at run time. The multiplier offers full precision regardless of the sign representation and can be registered using dedicated registers located at the input register stage.

Multiplier Modes

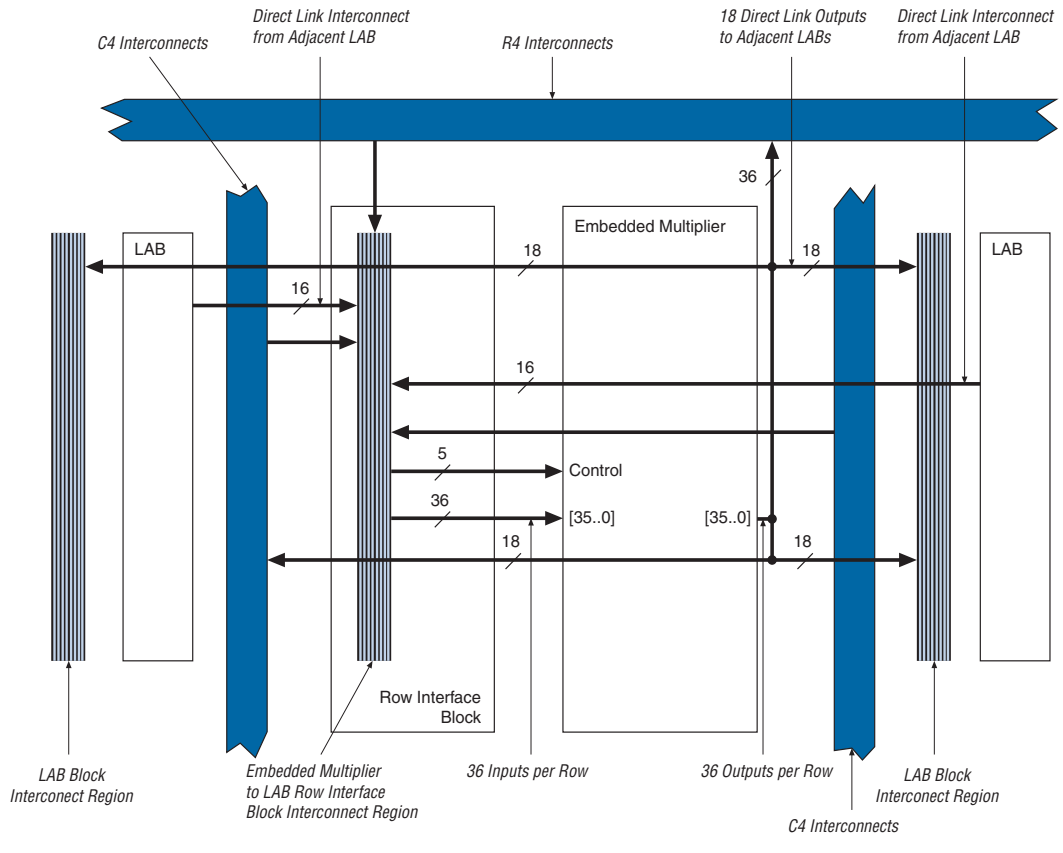
Table 2–12 summarizes the different modes that the embedded multipliers can operate in.

Multiplier Mode	Description
18-bit Multiplier	An embedded multiplier can be configured to support a single 18×18 multiplier for operand widths up to 18 bits. All 18-bit multiplier inputs and results can be registered independently. The multiplier operands can accept signed integers, unsigned integers, or a combination of both.
9-bit Multiplier	An embedded multiplier can be configured to support two 9×9 independent multipliers for operand widths up to 9-bits. Both 9-bit multiplier inputs and results can be registered independently. The multiplier operands can accept signed integers, unsigned integers or a combination of both. There is only one <code>signa</code> signal to control the sign representation of both data A inputs and one <code>signb</code> signal to control the sign representation of both data B inputs of the 9-bit multipliers within the same dedicated multiplier.

Embedded Multiplier Routing Interface

The R4, C4, and direct link interconnects from adjacent LABs drive the embedded multiplier row interface interconnect. The embedded multipliers can communicate with LABs on either the left or right side through these row resources or with LAB columns on either the right or left with the column resources. Up to 16 direct link input connections to the embedded multiplier are possible from the left adjacent LABs and another 16 possible from the right adjacent LAB. Embedded multiplier outputs can also connect to left and right LABs through 18 direct link interconnects each. **Figure 2-19** shows the embedded multiplier to logic array interface.

Figure 2-19. Embedded Multiplier LAB Row Interface



There are five dynamic control input signals that feed the embedded multiplier: `signa`, `signb`, `clk`, `clkena`, and `aclr`. `signa` and `signb` can be registered to match the data signal input path. The same `clk`, `clkena`, and `aclr` signals feed all registers within a single embedded multiplier.



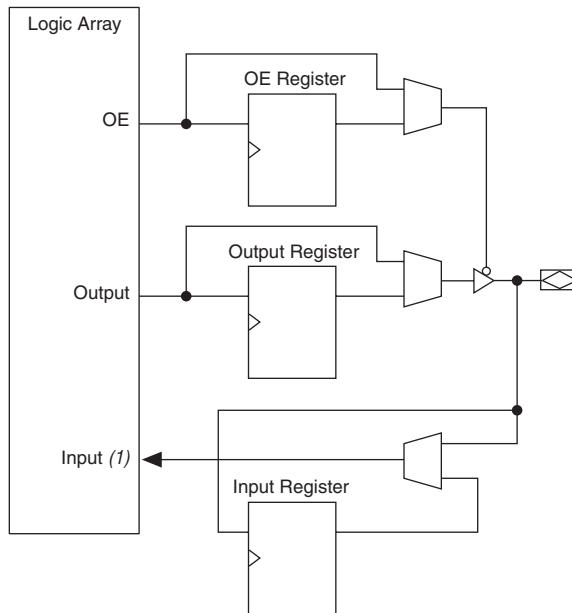
For more information on Cyclone II embedded multipliers, see the *Embedded Multipliers in Cyclone II Devices* chapter.

I/O Structure & Features

IOEs support many features, including:

- Differential and single-ended I/O standards
- 3.3-V, 64- and 32-bit, 66- and 33-MHz PCI compliance
- Joint Test Action Group (JTAG) boundary-scan test (BST) support
- Output drive strength control
- Weak pull-up resistors during configuration
- Tri-state buffers
- Bus-hold circuitry
- Programmable pull-up resistors in user mode
- Programmable input and output delays
- Open-drain outputs
- DQ and DQS I/O pins
- V_{REF} pins

Cyclone II device IOEs contain a bidirectional I/O buffer and three registers for complete embedded bidirectional single data rate transfer. [Figure 2–20](#) shows the Cyclone II IOE structure. The IOE contains one input register, one output register, and one output enable register. You can use the input registers for fast setup times and output registers for fast clock-to-output times. Additionally, you can use the output enable (OE) register for fast clock-to-output enable timing. The Quartus II software automatically duplicates a single OE register that controls multiple output or bidirectional pins. You can use IOEs as input, output, or bidirectional pins.

Figure 2–20. Cyclone II IOE Structure**Note to Figure 2–20:**

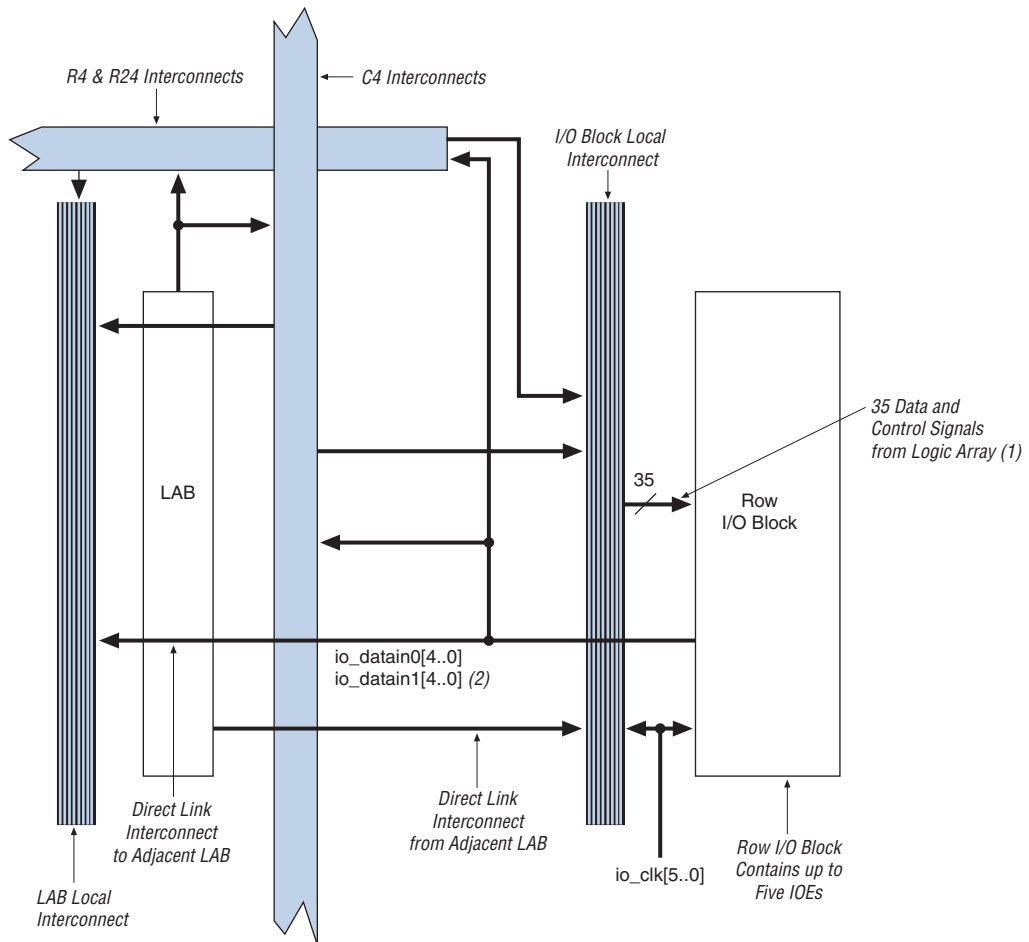
- (1) There are two paths available for combinational or registered inputs to the logic array. Each path contains a unique programmable delay chain.

The IOEs are located in I/O blocks around the periphery of the Cyclone II device. There are up to five IOEs per row I/O block and up to four IOEs per column I/O block (column I/O blocks span two columns). The row I/O blocks drive row, column (only C4 interconnects), or direct link interconnects. The column I/O blocks drive column interconnects.

Figure 2–21 shows how a row I/O block connects to the logic array.

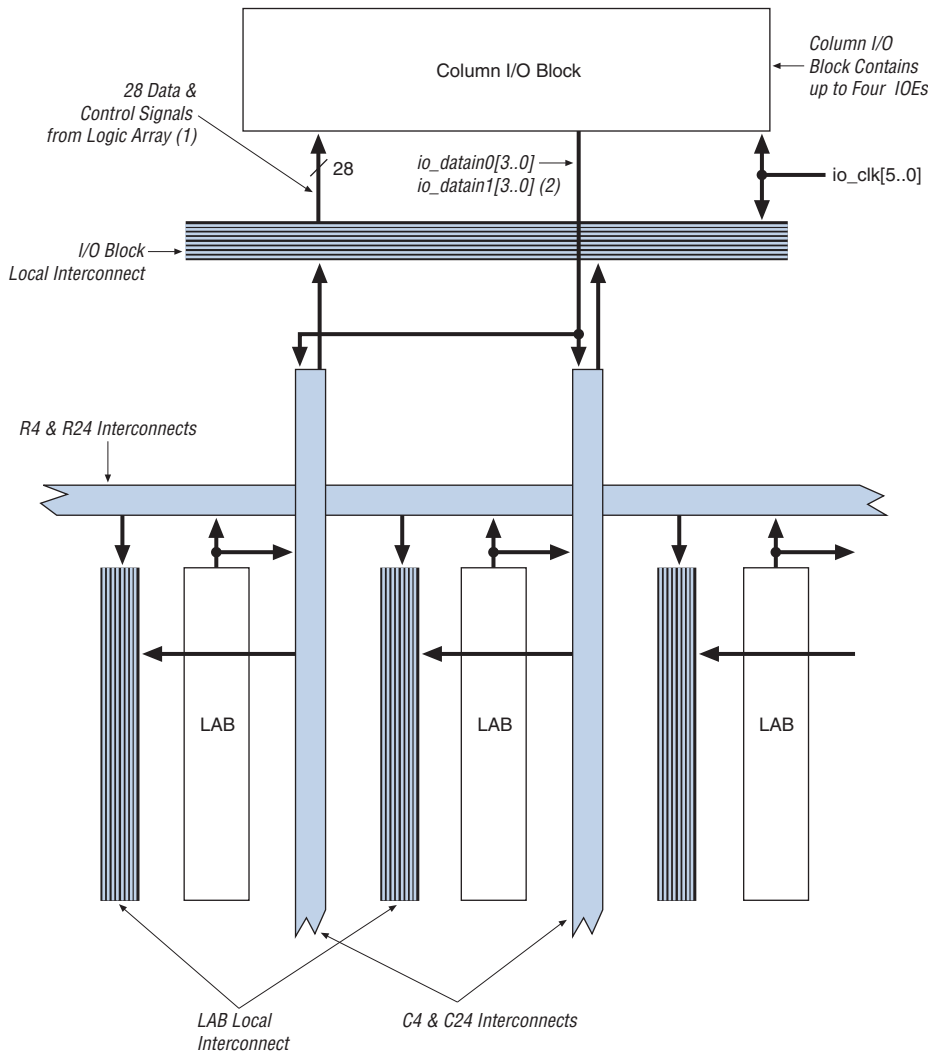
Figure 2–22 shows how a column I/O block connects to the logic array.

Figure 2–21. Row I/O Block Connection to the Interconnect

**Notes to Figure 2–21:**

- (1) The 35 data and control signals consist of five data out lines, $io_dataout[4..0]$, five output enables, $io_coe[4..0]$, five input clock enables, $io_cce_in[4..0]$, five output clock enables, $io_cce_out[4..0]$, five clocks, $io_cclk[4..0]$, five asynchronous clear signals, $io_caclr[4..0]$, and five synchronous clear signals, $io_csclr[4..0]$.
- (2) Each of the five IOEs in the row I/O block can have two io_datain (combinational or registered) inputs.

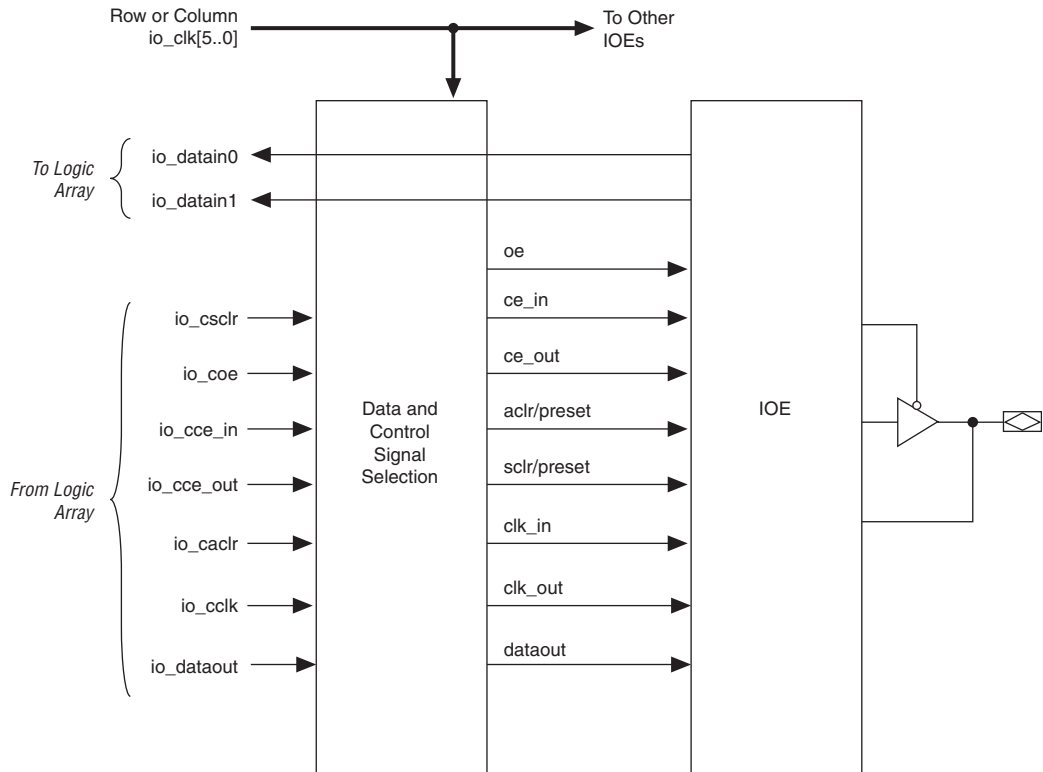
Figure 2–22. Column I/O Block Connection to the Interconnect

**Notes to Figure 2–22:**

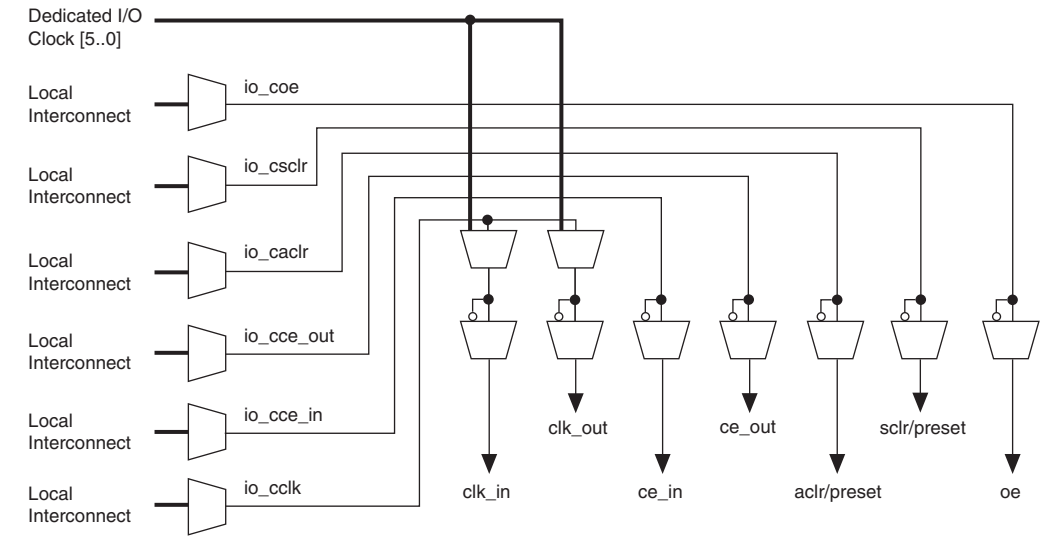
- (1) The 28 data and control signals consist of four data out lines, $io_dataout[3..0]$, four output enables, $io_coe[3..0]$, four input clock enables, $io_cce_in[3..0]$, four output clock enables, $io_cce_out[3..0]$, four clocks, $io_clk[3..0]$, four asynchronous clear signals, $io_cac1r[3..0]$, and four synchronous clear signals, $io_csc1r[3..0]$.
- (2) Each of the four IOEs in the column I/O block can have two io_datain (combinational or registered) inputs.

The pin's data in signals can drive the logic array. The logic array drives the control and data signals, providing a flexible routing resource. The row or column IOE clocks, `io_clk[5..0]`, provide a dedicated routing resource for low-skew, high-speed clocks. The global clock network generates the IOE clocks that feed the row or column I/O regions (see “Global Clock Network & Phase-Locked Loops” on page 2-16). Figure 2-23 illustrates the signal paths through the I/O block.

Figure 2-23. Signal Path Through the I/O Block

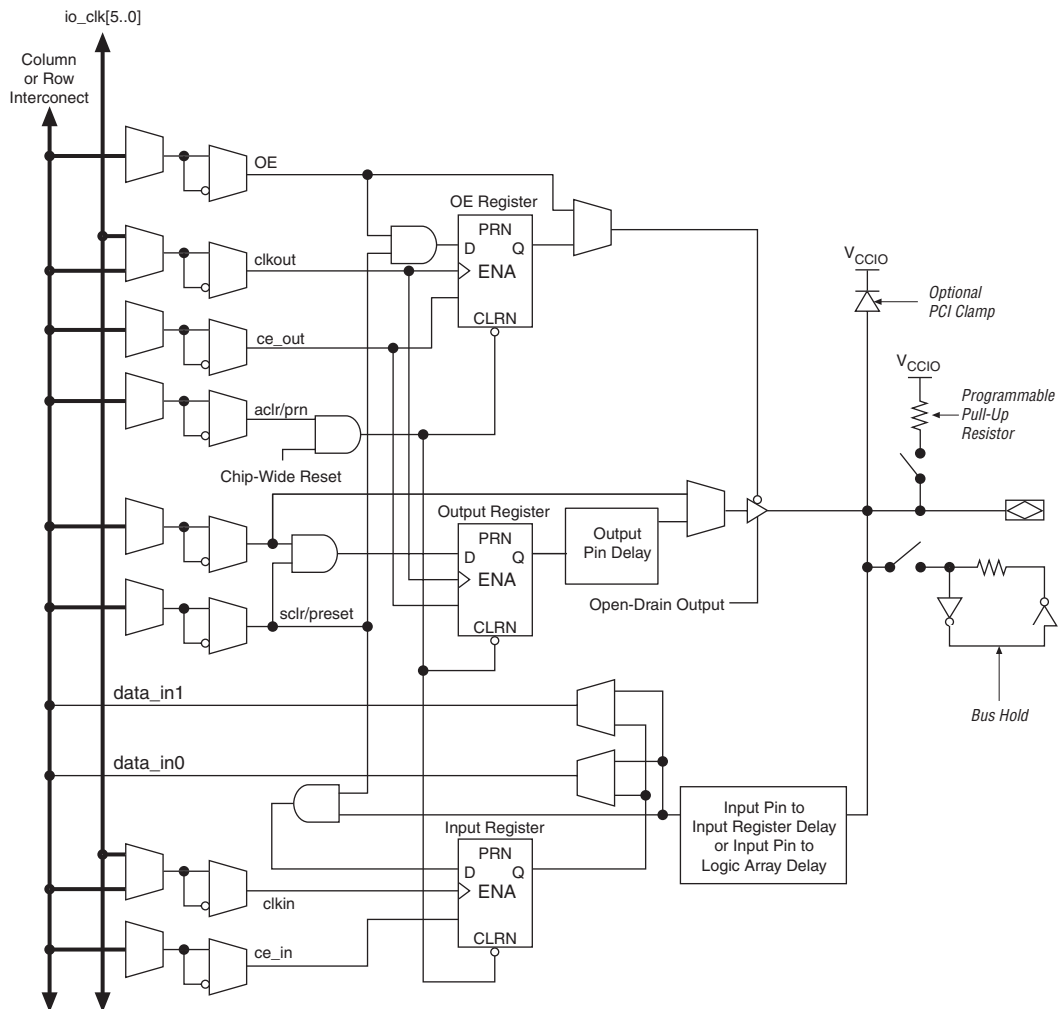


Each IOE contains its own control signal selection for the following control signals: `oe`, `ce_in`, `ce_out`, `aclr/preset`, `sclr/preset`, `clk_in`, and `clk_out`. Figure 2-24 illustrates the control signal selection.

Figure 2–24. Control Signal Selection per IOE

In normal bidirectional operation, you can use the input register for input data requiring fast setup times. The input register can have its own clock input and clock enable separate from the OE and output registers. You can use the output register for data requiring fast clock-to-output performance. The OE register is available for fast clock-to-output enable timing. The OE and output register share the same clock source and the same clock enable source from the local interconnect in the associated LAB, dedicated I/O clocks, or the column and row interconnects. All registers share `sclr` and `acclr`, but each register can individually disable `sclr` and `acclr`. [Figure 2–25](#) shows the IOE in bidirectional configuration.

Figure 2–25. Cyclone II IOE in Bidirectional I/O Configuration



The Cyclone II device IOE includes programmable delays to ensure zero hold times, minimize setup times, or increase clock to output times.

A path in which a pin directly drives a register may require a programmable delay to ensure zero hold time, whereas a path in which a pin drives a register through combinational logic may not require the delay. Programmable delays decrease input-pin-to-logic-array and IOE input register delays. The Quartus II Compiler can program these delays to automatically minimize setup time while providing a zero hold time.

Programmable delays can increase the register-to-pin delays for output registers. Table 2–13 shows the programmable delays for Cyclone II devices.

Programmable Delays	Quartus II Logic Option
Input pin to logic array delay	Input delay from pin to internal cells
Input pin to input register delay	Input delay from pin to input register
Output pin delay	Delay from output register to output pin

There are two paths in the IOE for an input to reach the logic array. Each of the two paths can have a different delay. This allows you to adjust delays from the pin to internal LE registers that reside in two different areas of the device. You set the two combinational input delays by selecting different delays for two different paths under the **Input delay from pin to internal cells logic** option in the Quartus II software. However, if the pin uses the input register, one of delays is disregarded because the IOE only has two paths to internal logic. If the input register is used, the IOE uses one input path. The other input path is then available for the combinational path, and only one input delay assignment is applied.

The IOE registers in each I/O block share the same source for clear or preset. You can program preset or clear for each individual IOE, but both features cannot be used simultaneously. You can also program the registers to power up high or low after configuration is complete. If programmed to power up low, an asynchronous clear can control the registers. If programmed to power up high, an asynchronous preset can control the registers. This feature prevents the inadvertent activation of another device's active-low input upon power up. If one register in an IOE uses a preset or clear signal then all registers in the IOE must use that same signal if they require preset or clear. Additionally a synchronous reset signal is available for the IOE registers.

External Memory Interfacing

Cyclone II devices support a broad range of external memory interfaces such as SDR SDRAM, DDR SDRAM, DDR2 SDRAM, and QDR II SRAM external memories. Cyclone II devices feature dedicated high-speed interfaces that transfer data between external memory devices at up to 167 MHz/333 Mbps for DDR and DDR2 SDRAM devices and 167 MHz/667 Mbps for QDR II SRAM devices. The programmable DQS delay chain allows you to fine tune the phase shift for the input clocks or strobes to properly align clock edges as needed to capture data.

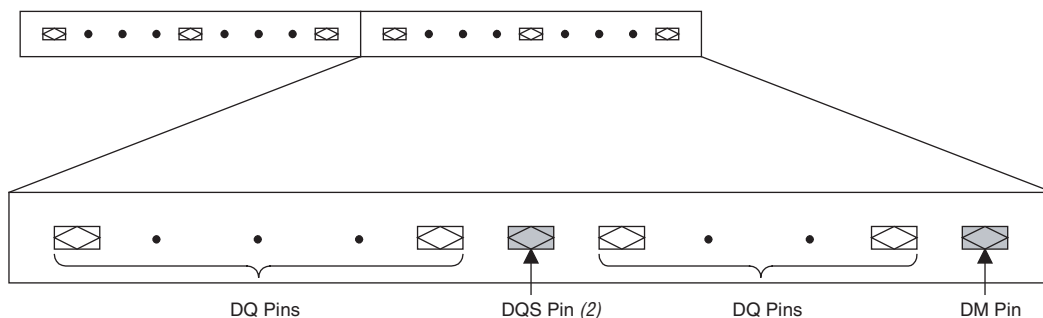
In Cyclone II devices, all the I/O banks support SDR and DDR SDRAM memory up to 167 MHz/333 Mbps. All I/O banks support DQS signals with the DQ bus modes of $\times 8/\times 9$, or $\times 16/\times 18$. Table 2–14 shows the external memory interfaces supported in Cyclone II devices.

Memory Standard	I/O Standard	Maximum Bus Width	Maximum Clock Rate Supported (MHz)	Maximum Data Rate Supported (Mbps)
SDR SDRAM	LVTTTL (2)	72	167	167
DDR SDRAM	SSTL-2 class I (2)	72	167	333 (1)
	SSTL-2 class II (2)	72	133	267 (1)
DDR2 SDRAM	SSTL-18 class I (2)	72	167	333 (1)
	SSTL-18 class II (3)	72	125	250 (1)
QDR II SRAM (4)	1.8-V HSTL class I (2)	36	167	668 (1)
	1.8-V HSTL class II (3)	36	100	400 (1)

Notes to Table 2–14:

- (1) The data rate is for designs using the Clock Delay Control circuitry.
- (2) The I/O standards are supported on all the I/O banks of the Cyclone II device.
- (3) The I/O standards are supported only on the I/O banks on the top and bottom of the Cyclone II device.
- (4) For maximum performance, Altera recommends using the 1.8-V HSTL I/O standard because of higher I/O drive strength. QDR II SRAM devices also support the 1.5-V HSTL I/O standard.

Cyclone II devices use data (DQ), data strobe (DQS), and clock pins to interface with external memory. Figure 2–26 shows the DQ and DQS pins in the $\times 8/\times 9$ mode.

Figure 2–26. Cyclone II Device DQ & DQS Groups in $\times 8/\times 9$ Mode *Notes (1), (2)***Notes to Figure 2–26:**

- (1) Each DQ group consists of a DQS pin, DM pin, and up to nine DQ pins.
- (2) This is an idealized pin layout. For actual pin layout, refer to the pin table.

Cyclone II devices support the data strobe or read clock signal (DQS) used in DDR and DDR2 SDRAM. Cyclone II devices can use either bidirectional data strobes or unidirectional read clocks. The dedicated external memory interface in Cyclone II devices also includes programmable delay circuitry that can shift the incoming DQS signals to center align the DQS signals within the data window.

The DQS signal is usually associated with a group of data (DQ) pins. The phase-shifted DQS signals drive the global clock network, which is used to clock the DQ signals on internal LE registers.

Table 2–15 shows the number of DQ pin groups per device.

Table 2–15. Cyclone II DQS & DQ Bus Mode Support (Part 1 of 2) *Note (1)*

Device	Package	Number of $\times 8$ Groups	Number of $\times 9$ Groups (5), (6)	Number of $\times 16$ Groups	Number of $\times 18$ Groups (5), (6)
EP2C5	144-pin TQFP (2)	3	3	0	0
	208-pin PQFP	7 (3)	4	3	3
EP2C8	144-pin TQFP (2)	3	3	0	0
	208-pin PQFP	7 (3)	4	3	3
	256-pin FineLine BGA®	8 (3)	4	4	4
EP2C15	256-pin FineLine BGA	8	4	4	4
	484-pin FineLine BGA	16 (4)	8	8	8
EP2C20	256-pin FineLine BGA	8	4	4	4
	484-pin FineLine BGA	16 (4)	8	8	8

Table 2–15. Cyclone II DQS & DQ Bus Mode Support (Part 2 of 2) *Note (1)*

Device	Package	Number of ×8 Groups	Number of ×9 Groups (5), (6)	Number of ×16 Groups	Number of ×18 Groups (5), (6)
EP2C35	484-pin FineLine BGA	16 (4)	8	8	8
	672-pin FineLine BGA	20 (4)	8	8	8
EP2C50	484-pin FineLine BGA	16 (4)	8	8	8
	672-pin FineLine BGA	20 (4)	8	8	8
EP2C70	672-pin FineLine BGA	20 (4)	8	8	8
	896-pin FineLine BGA	20 (4)	8	8	8

Notes to Table 2–15:

- (1) Numbers are preliminary.
- (2) EP2C5 and EP2C8 devices in the 144-pin TQFP package do not have any DQ pin groups in I/O bank 1.
- (3) Because of available clock resources, only a total of 6 DQ/DQS groups can be implemented.
- (4) Because of available clock resources, only a total of 14 DQ/DQS groups can be implemented.
- (5) The ×9 DQS/DQ groups are also used as ×8 DQS/DQ groups. The ×18 DQS/DQ groups are also used as ×16 DQS/DQ groups.
- (6) For QDRI implementation, if you connect the D ports (write data) to the Cyclone II DQ pins, the total available ×9 DQS /DQ and ×18 DQS/DQ groups are half of that shown in Table 2–15.

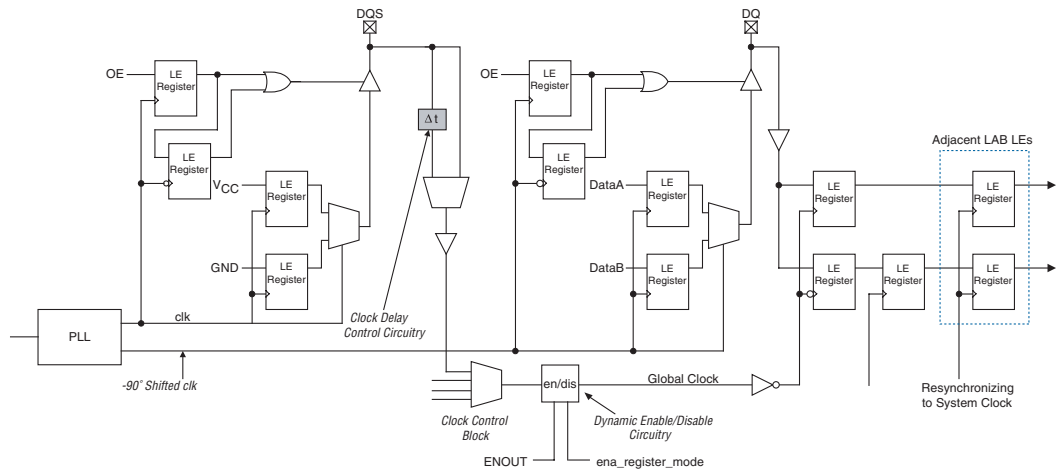
You can use any of the DQ pins for the parity pins in Cyclone II devices. The Cyclone II device family supports parity in the ×8/×9, and ×16/×18 mode. There is one parity bit available per eight bits of data pins.

The data mask, DM, pins are required when writing to DDR SDRAM and DDR2 SDRAM devices. A low signal on the DM pin indicates that the write is valid. If the DM signal is high, the memory masks the DQ signals. In Cyclone II devices, the DM pins are assigned and are the preferred pins. Each group of DQS and DQ signals requires a DM pin.

When using the Cyclone II I/O banks to interface with the DDR memory, at least one PLL with two clock outputs is needed to generate the system and write clock. The system clock is used to clock the DQS write signals, commands, and addresses. The write clock is shifted by –90° from the system clock and is used to clock the DQ signals during writes.

Figure 2–27 illustrates DDR SDRAM interfacing from the I/O through the dedicated circuitry to the logic array.

Figure 2-27. DDR SDRAM Interfacing



For more information on Cyclone II external memory interfaces, see the *External Memory Interfaces* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Programmable Drive Strength

The output buffer for each Cyclone II device I/O pin has a programmable drive strength control for certain I/O standards. The LVTTTL, LVCMOS, SSTL-2 class I and II, SSTL-18 class I and II, HSTL-18 class I and II, and HSTL-1.5 class I and II standards have several levels of drive strength that you can control. Using minimum settings provides signal slew rate control to reduce system noise and signal overshoot. Table 2-16 shows the possible settings for the I/O standards with drive strength control.

Table 2-16. Programmable Drive Strength (Part 1 of 2) *Note (1)*

I/O Standard	I_{OH}/I_{OL} Current Strength Setting (mA)	
	Top & Bottom I/O Pins	Side I/O Pins
LVTTTL (3.3 V)	4	4
	8	8
	12	12
	16	16
	20	20
	24	24
LVCMOS (3.3 V)	4	4
	8	8
	12	12
	16	
	20	
	24	
LVTTTL/LVCMOS (2.5 V)	4	4
	8	8
	12	
	16	
LVTTTL/LVCMOS (1.8 V)	2	2
	4	4
	6	6
	8	8
	10	10
	12	12

Table 2–16. Programmable Drive Strength (Part 2 of 2) *Note (1)*

I/O Standard	I _{OH} /I _{OL} Current Strength Setting (mA)	
	Top & Bottom I/O Pins	Side I/O Pins
LVCMOS (1.5 V)	2	2
	4	4
	6	6
	8	
SSTL-2 class I	8	8
	12	12
SSTL-2 class II	16	16
	20	
	24	
SSTL-18 class I	6	6
	8	8
	10	10
	12	
SSTL-18 class II	16	
	18	
HSTL-18 class I	8	8
	10	10
	12	12
HSTL-18 class II	16	
	18	
	20	
HSTL-15 class I	8	8
	10	
	12	
HSTL-15 class II	16	

Note to Table 2–16:

- (1) The default current in the Quartus II software is the maximum setting for each I/O standard.

Open-Drain Output

Cyclone II devices provide an optional open-drain (equivalent to an open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (that is, interrupt and write-enable signals) that can be asserted by any of several devices.

Slew Rate Control

Slew rate control is performed by using programmable output drive strength.

Bus Hold

Each Cyclone II device user I/O pin provides an optional bus-hold feature. The bus-hold circuitry can hold the signal on an I/O pin at its last-driven state. Since the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not necessary to hold a signal level when the bus is tri-stated.

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage where noise can cause unintended high-frequency switching. You can select this feature individually for each I/O pin. The bus-hold output drives no higher than V_{CCIO} to prevent overdriving signals.



If the bus-hold feature is enabled, the device cannot use the programmable pull-up option. Disable the bus-hold feature when the I/O pin is configured for differential signals. Bus hold circuitry is not available on the dedicated clock pins.

The bus-hold circuitry is only active after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

The bus-hold circuitry uses a resistor with a nominal resistance (R_{BH}) of approximately 7 k Ω to pull the signal level to the last-driven state. Refer to the *DC Characteristics & Timing Specifications* chapter in Volume 1 of the *Cyclone II Device Handbook* for the specific sustaining current for each V_{CCIO} voltage level driven through the resistor and overdrive current used to identify the next driven input level.

Programmable Pull-Up Resistor

Each Cyclone II device I/O pin provides an optional programmable pull-up resistor during user mode. If you enable this feature for an I/O pin, the pull-up resistor (typically 25 k Ω) holds the output to the V_{CCIO} level of the output pin's bank.



If the programmable pull-up is enabled, the device cannot use the bus-hold feature. The programmable pull-up resistors are not supported on the dedicated configuration, JTAG, and dedicated clock pins.

Advanced I/O Standard Support

Table 2–17 shows the I/O standards supported by Cyclone II devices and which I/O pins support them.

I/O Standard	Type	V _{CCIO} Level		Top & Bottom I/O Pins		Side I/O Pins		
		Input	Output	CLK, DQS	User I/O Pins	CLK, DQS	PLL_OUT	User I/O Pins
3.3-V LVTTTL and LVCMOS (1)	Single ended	3.3 V / 2.5 V	3.3 V	✓	✓	✓	✓	✓
2.5-V LVTTTL and LVCMOS	Single ended	3.3 V / 2.5 V	2.5 V	✓	✓	✓	✓	✓
1.8-V LVTTTL and LVCMOS	Single ended	1.8 V / 1.5 V	1.8 V	✓	✓	✓	✓	✓
1.5-V LVCMOS	Single ended	1.8 V / 1.5 V	1.5 V	✓	✓	✓	✓	✓
SSTL-2 class I	Voltage referenced	2.5 V	2.5 V	✓	✓	✓	✓	✓
SSTL-2 class II	Voltage referenced	2.5 V	2.5 V	✓	✓	✓	✓	✓
SSTL-18 class I	Voltage referenced	1.8 V	1.8 V	✓	✓	✓	✓	✓
SSTL-18 class II	Voltage referenced	1.8 V	1.8 V	✓	✓	(2)	(2)	(2)
HSTL-18 class I	Voltage referenced	1.8 V	1.8 V	✓	✓	✓	✓	✓
HSTL-18 class II	Voltage referenced	1.8 V	1.8 V	✓	✓	(2)	(2)	(2)
HSTL-15 class I	Voltage referenced	1.5 V	1.5 V	✓	✓	✓	✓	✓
HSTL-15 class II	Voltage referenced	1.5 V	1.5 V	✓	✓	(2)	(2)	(2)
PCI and PCI-X (1) (3)	Single ended	3.3 V	3.3 V			✓	✓	✓
Differential SSTL-2 class I or class II	Pseudo differential (4)	(5)	2.5 V				✓	
		2.5 V	(5)	✓ (6)		✓ (6)		
Differential SSTL-18 class I or class II	Pseudo differential (4)	(5)	1.8 V				✓ (7)	
		1.8 V	(5)	✓ (6)		✓ (6)		

Table 2–17. Cyclone II Supported I/O Standards & Constraints (Part 2 of 2)

I/O Standard	Type	V _{CCIO} Level		Top & Bottom I/O Pins		Side I/O Pins		
		Input	Output	CLK, DQS	User I/O Pins	CLK, DQS	PLL_OUT	User I/O Pins
Differential HSTL-15 class I or class II	Pseudo differential (4)	(5)	1.5 V				✓ (7)	
		1.5 V	(5)	✓ (6)		✓ (6)		
Differential HSTL-18 class I or class II	Pseudo differential (4)	(5)	1.8 V				✓ (7)	
		1.8 V	(5)	✓ (6)		✓ (6)		
LVDS	Differential	2.5 V	2.5 V	✓	✓	✓	✓	✓
RSDS and mini-LVDS (8)	Differential	(5)	2.5 V		✓		✓	✓
LVPECL (9)	Differential	3.3 V/ 2.5 V/ 1.8 V/ 1.5 V	(5)	✓		✓		

Notes to Table 2–17:

- (1) To drive inputs higher than V_{CCIO} but less than 4.0 V, disable the PCI clamping diode and turn on the **Allow LVTTTL and LVCMOS input levels to overdrive input buffer** option in the Quartus II software.
- (2) These pins support SSTL-18 class II and 1.8- and 1.5-V HSTL class II inputs.
- (3) PCI-X does not meet the IV curve requirement at the linear region. PCI-clamp diode is not available on top and bottom I/O pins.
- (4) Pseudo-differential HSTL and SSTL outputs use two single-ended outputs with the second output programmed as inverted. Pseudo-differential HSTL and SSTL inputs treat differential inputs as two single-ended HSTL and SSTL inputs and only decode one of them.
- (5) This I/O standard is not supported on these I/O pins.
- (6) This I/O standard is only supported on the dedicated clock pins.
- (7) PLL_OUT does not support differential SSTL-18 class II and differential 1.8 and 1.5-V HSTL class II.
- (8) mini-LVDS and RSDS are only supported on output pins.
- (9) LVPECL is only supported on clock inputs.



For more information on Cyclone II supported I/O standards, see the *Selectable I/O Standards in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

High-Speed Differential Interfaces

Cyclone II devices can transmit and receive data through LVDS signals at a data rate of up to 640 Mbps and 805 Mbps, respectively. For the LVDS transmitter and receiver, the Cyclone II device's input and output pins support serialization and deserialization through internal logic.

The reduced swing differential signaling (RSDS) and mini-LVDS standards are derivatives of the LVDS standard. The RSDS and mini-LVDS I/O standards are similar in electrical characteristics to LVDS, but have a smaller voltage swing and therefore provide increased power benefits and reduced electromagnetic interference (EMI). Cyclone II devices support the RSDS and mini-LVDS I/O standards at data rates up to 311 Mbps at the transmitter.

A subset of pins in each I/O bank (on both rows and columns) support the high-speed I/O interface. The dual-purpose LVDS pins require an external-resistor network at the transmitter channels in addition to 100- Ω termination resistors on receiver channels. These pins do not contain dedicated serialization or deserialization circuitry. Therefore, internal logic performs serialization and deserialization functions.

Cyclone II pin tables list the pins that support the high-speed I/O interface. The number of LVDS channels supported in each device family member is listed in [Table 2–18](#).

Device	Pin Count	Number of LVDS Channels (1)
EP2C5	144	31 (35)
	208	56 (60)
	256	61 (65)
EP2C8	144	29 (33)
	208	53 (57)
	256	75 (79)
EP2C15	256	52 (60)
	484	128 (136)
EP2C20	240	45 (53)
	256	52 (60)
	484	128 (136)
EP2C35	484	131 (139)
	672	201 (209)
EP2C50	484	119 (127)
	672	189 (197)

Table 2–18. Cyclone II Device LVDS Channels (Part 2 of 2)

Device	Pin Count	Number of LVDS Channels ⁽¹⁾
EP2C70	672	160 (168)
	896	257 (265)

Note to Table 2–18:

- (1) The first number represents the number of bidirectional I/O pins which can be used as inputs or outputs. The number in parenthesis includes dedicated clock input pin pairs which can only be used as inputs.

You can use I/O pins and internal logic to implement a high-speed I/O receiver and transmitter in Cyclone II devices. Cyclone II devices do not contain dedicated serialization or deserialization circuitry. Therefore, shift registers, internal PLLs, and IOEs are used to perform serial-to-parallel conversions on incoming data and parallel-to-serial conversion on outgoing data.

The maximum internal clock frequency for a receiver and for a transmitter is 402.5 MHz. The maximum input data rate of 805 Mbps and the maximum output data rate of 640 Mbps is only achieved when DDIO registers are used. The LVDS standard does not require an input reference voltage, but it does require a 100- Ω termination resistor between the two signals at the input buffer. An external resistor network is required on the transmitter side.



For more information on Cyclone II differential I/O interfaces, see the *High-Speed Differential Interfaces in Cyclone II Devices* chapter in Volume 1 of the *Cyclone II Device Handbook*.

Series On-Chip Termination

On-chip termination helps to prevent reflections and maintain signal integrity. This also minimizes the need for external resistors in high pin count ball grid array (BGA) packages. Cyclone II devices provide I/O driver on-chip impedance matching and on-chip series termination for single-ended outputs and bidirectional pins.

Cyclone II devices support driver impedance matching to the impedance of the transmission line, typically 25 or 50 Ω . When used with the output drivers, on-chip termination sets the output driver impedance to 25 or 50 Ω . Cyclone II devices also support I/O driver series termination ($R_S = 50 \Omega$) for SSTL-2 and SSTL-18. Table 2–19 lists the I/O standards that support impedance matching and series termination.

I/O Standards	Target R_S (Ω)	V_{CCIO} (V)
3.3-V LVTTTL and LVCMOS	25 (2)	3.3
2.5-V LVTTTL and LVCMOS	50 (2)	2.5
1.8-V LVTTTL and LVCMOS	50 (2)	1.8
SSTL-2 class I	50 (2)	2.5
SSTL-18 class I	50 (2)	1.8

Notes to Table 2–19:

- (1) Supported conditions are $V_{CCIO} = V_{CCIO} \pm 50$ mV.
- (2) These R_S values are nominal values. Actual impedance varies across process, voltage, and temperature conditions.



The recommended frequency range of operation is pending silicon characterization.

On-chip series termination can be supported on any I/O bank. V_{CCIO} and V_{REF} must be compatible for all I/O pins in order to enable on-chip series termination in a given I/O bank. I/O standards that support different R_S values can reside in the same I/O bank as long as their V_{CCIO} and V_{REF} are not conflicting.



When using on-chip series termination, programmable drive strength is not available.

Impedance matching is implemented using the capabilities of the output driver and is subject to a certain degree of variation, depending on the process, voltage and temperature. The actual tolerance is pending silicon characterization.

I/O Banks

The I/O pins on Cyclone II devices are grouped together into I/O banks and each bank has a separate power bus. EP2C5 and EP2C8 devices have four I/O banks (see [Figure 2–28](#)), while EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices have eight I/O banks (see [Figure 2–29](#)).

Each device I/O pin is associated with one I/O bank. To accommodate voltage-referenced I/O standards, each Cyclone II I/O bank has a VREF bus. Each bank in EP2C5, EP2C8, EP2C15, EP2C20, EP2C35, and EP2C50 devices supports two VREF pins and each bank of EP2C70 supports four VREF pins. When using the VREF pins, each VREF pin must be properly connected to the appropriate voltage level. In the event these pins are not used as VREF pins, they may be used as regular I/O pins.

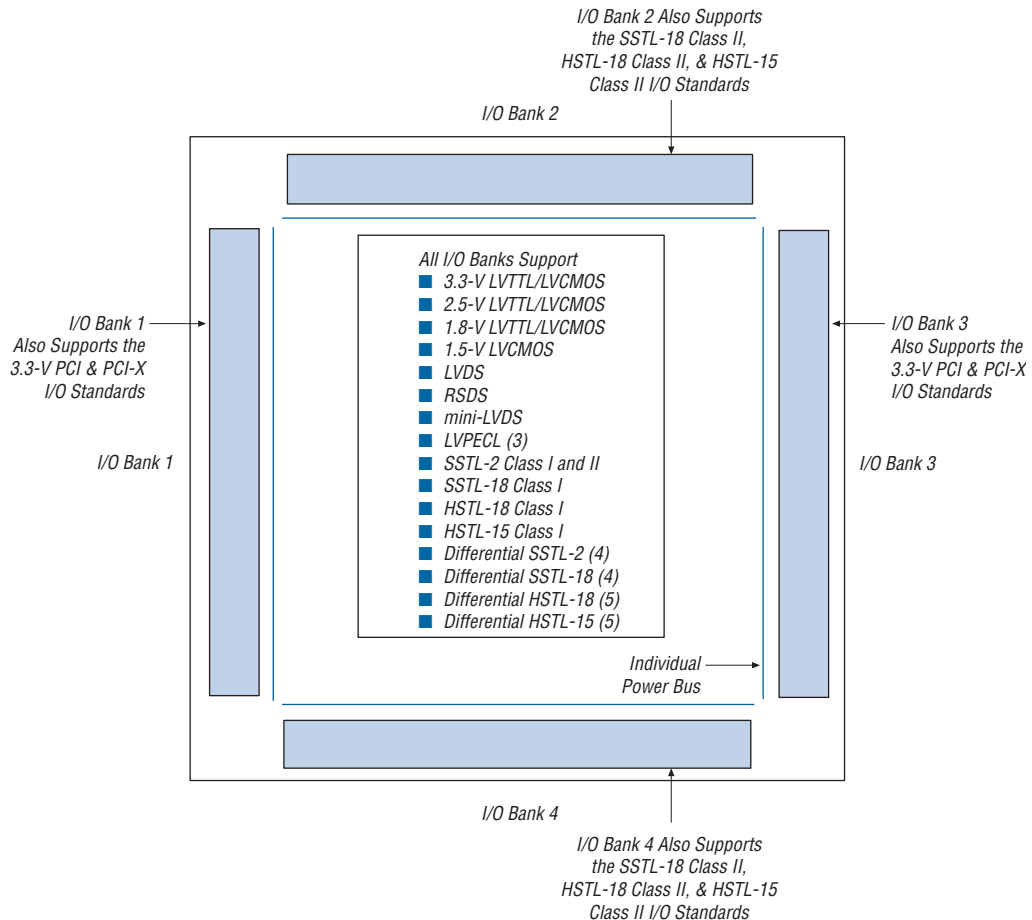
The top and bottom I/O banks (banks 2 and 4 in EP2C5 and EP2C8 devices and banks 3, 4, 7, and 8 in EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) support all I/O standards listed in [Table 2–17](#), except the PCI/PCI-X I/O standards. The left and right side I/O banks (banks 1 and 3 in EP2C5 and EP2C8 devices and banks 1, 2, 5, and 6 in EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) support I/O standards listed in [Table 2–17](#), except SSTL-18 class II, HSTL-18 class II, and HSTL-15 class II I/O standards. See [Table 2–17](#) for a complete list of supported I/O standards.

The top and bottom I/O banks (banks 2 and 4 in EP2C5 and EP2C8 devices and banks 3, 4, 7, and 8 in EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) support DDR2 memory up to 167 MHz/333 Mbps and QDR memory up to 167 MHz/668 Mbps. The left and right side I/O banks (1 and 3 of EP2C5 and EP2C8 devices and 1, 2, 5, and 6 of EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices) only support SDR and DDR SDRAM interfaces. All the I/O banks of the Cyclone II devices support SDR memory up to 167 MHz/167 Mbps and DDR memory up to 167 MHz/333 Mbps.



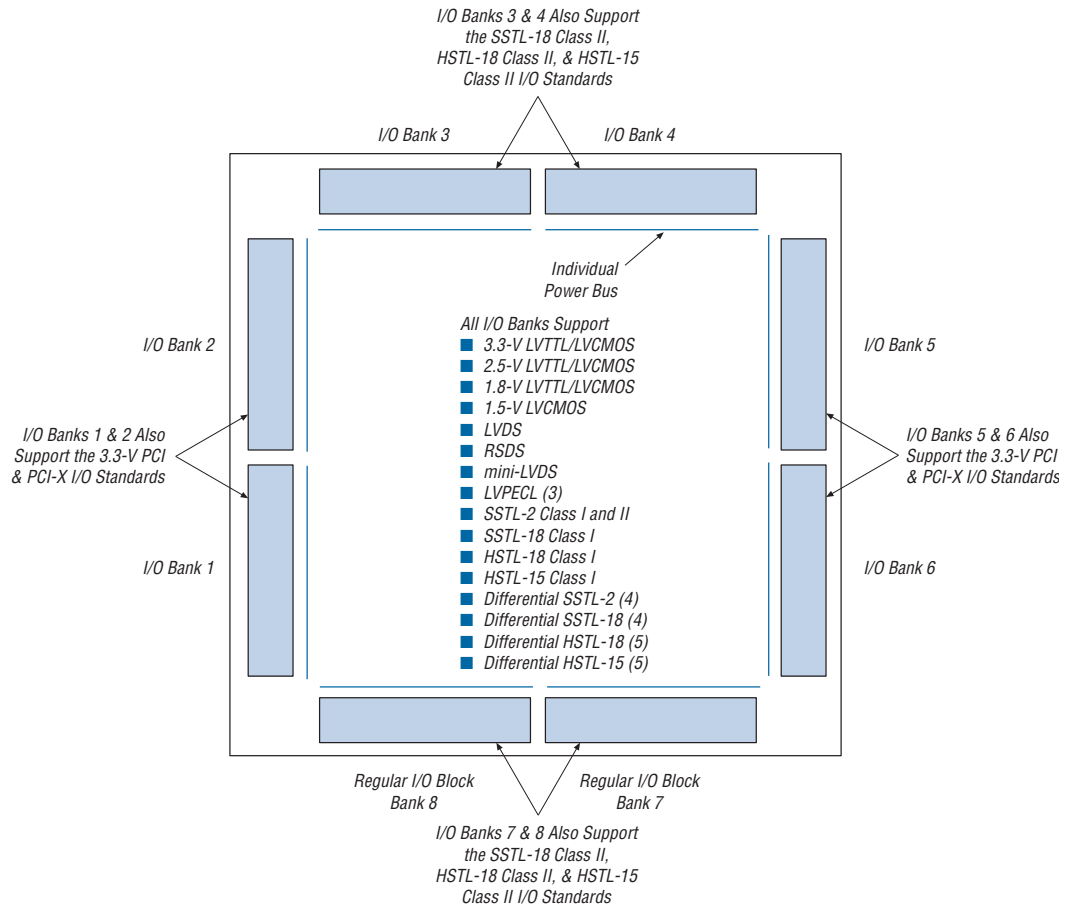
DDR2 and QDR II interfaces may be implemented in Cyclone II side banks if the use of class I I/O standard is acceptable.

Figure 2–28. EP2C5 & EP2C8 I/O Banks Notes (1), (2)



Notes to Figure 2–28:

- (1) This is a top view of the silicon die.
- (2) This is a graphic representation only. Refer to the pin list and the Quartus II software for exact pin locations.
- (3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.
- (4) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.
- (5) The differential 1.8-V and 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

Figure 2–29. EP2C15, EP2C20, EP2C35, EP2C50 & EP2C70 I/O Banks Notes (1), (2)**Notes to Figure 2–29:**

- (1) This is a top view of the silicon die.
- (2) This is a graphic representation only. Refer to the pin list and the Quartus II software for exact pin locations.
- (3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.
- (4) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.
- (5) The differential 1.8-V and 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

Each I/O bank has its own VCCIO pins. A single device can support 1.5-V, 1.8-V, 2.5-V, and 3.3-V interfaces; each individual bank can support a different standard with different I/O voltages. Each bank also has dual-purpose VREF pins to support any one of the voltage-referenced

standards (e.g., SSTL-2) independently. If an I/O bank does not use voltage-referenced standards, the V_{REF} pins are available as user I/O pins.

Each I/O bank can support multiple standards with the same V_{CCIO} for input and output pins. For example, when V_{CCIO} is 3.3-V, a bank can support LVTTTL, LVCMOS, and 3.3-V PCI for inputs and outputs. Voltage-referenced standards can be supported in an I/O bank using any number of single-ended or differential standards as long as they use the same V_{REF} and a compatible V_{CCIO} value.

MultiVolt I/O Interface

The Cyclone II architecture supports the MultiVolt I/O interface feature, which allows Cyclone II devices in all packages to interface with systems of different supply voltages. Cyclone II devices have one set of V_{CC} pins (V_{CCINT}) that power the internal device logic array and input buffers that use the LVPECL, LVDS, HSTL, or SSTL I/O standards. Cyclone II devices also have four or eight sets of V_{CC} pins (V_{CCIO}) that power the I/O output drivers and input buffers that use the LVTTTL, LVCMOS, or PCI I/O standards.

The Cyclone II V_{CCINT} pins must always be connected to a 1.2-V power supply. If the V_{CCINT} level is 1.2 V, then input pins are 1.5-V, 1.8-V, 2.5-V, and 3.3-V tolerant. The V_{CCIO} pins can be connected to either a 1.5-V, 1.8-V, 2.5-V, or 3.3-V power supply, depending on the output requirements. The output levels are compatible with systems of the same voltage as the power supply (i.e., when V_{CCIO} pins are connected to a 1.5-V power supply, the output levels are compatible with 1.5-V systems). When V_{CCIO} pins are connected to a 3.3-V power supply, the output high is 3.3-V and is compatible with 3.3-V systems. Table 2–20 summarizes Cyclone II MultiVolt I/O support.

Table 2–20. Cyclone II MultiVolt I/O Support (Part 1 of 2) *Note (1)*

V_{CCIO} (V)	Input Signal				Output Signal			
	1.5 V	1.8 V	2.5 V	3.3 V	1.5 V	1.8 V	2.5 V	3.3 V
1.5	✓	✓	✓ (2)	✓ (2)	✓			
1.8	✓ (4)	✓	✓ (2)	✓ (2)	✓ (3)	✓		
2.5			✓	✓	✓ (5)	✓ (5)	✓	

Table 2–20. Cyclone II MultiVolt I/O Support (Part 2 of 2) *Note (1)*

V_{CCIO} (V)	Input Signal				Output Signal			
	1.5 V	1.8 V	2.5 V	3.3 V	1.5 V	1.8 V	2.5 V	3.3 V
3.3			✓ (4)	✓	✓ (6)	✓ (6)	✓ (6)	✓

Notes to Table 2–20:

- (1) The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO} .
- (2) These input values overdrive the input buffer, so the pin leakage current is slightly higher than the default value. To drive inputs higher than V_{CCIO} but less than 4.0 V, disable the PCI clamping diode and turn on **Allow voltage overdrive for LVTTTL/LVC MOS input pins** option in Device setting option in the Quartus II software.
- (3) When $V_{CCIO} = 1.8\text{-V}$, a Cyclone II device can drive a 1.5-V device with 1.8-V tolerant inputs.
- (4) When $V_{CCIO} = 3.3\text{-V}$ and a 2.5-V input signal feeds an input pin or when $V_{CCIO} = 1.8\text{-V}$ and a 1.5-V input signal feeds an input pin, the V_{CCIO} supply current will be slightly larger than expected. The reason for this increase is that the input signal level does not drive to the V_{CCIO} rail, which causes the input buffer to not completely shut off.
- (5) When $V_{CCIO} = 2.5\text{-V}$, a Cyclone II device can drive a 1.5-V or 1.8-V device with 2.5-V tolerant inputs.
- (6) When $V_{CCIO} = 3.3\text{-V}$, a Cyclone II device can drive a 1.5-V, 1.8-V, or 2.5-V device with 3.3-V tolerant inputs.

Document Revision History

Table 2–21 shows the revision history for this document.

Date & Document Version	Changes Made	Summary of Changes
February 2007 v3.1	<ul style="list-style-type: none"> ● Added document revision history. ● Removed Table 2-1. ● Updated Figure 2–25. ● Added new <i>Note (1)</i> to Table 2–17. ● Added handpara note in “I/O Banks” section. ● Updated <i>Note (2)</i> to Table 2–20. 	<ul style="list-style-type: none"> ● Removed Drive Strength Control from Figure 2–25. ● Elaboration of DDR2 and QDR11 interfaces supported by I/O bank included.
November 2005 v2.1	<ul style="list-style-type: none"> ● Updated Table 2–7. ● Updated Figures 2–11 and 2–12. ● Updated Programmable Drive Strength table. ● Updated Table 2–16. ● Updated Table 2–18. ● Updated Table 2–19. 	
July 2005 v2.0	<ul style="list-style-type: none"> ● Updated technical content throughout. ● Updated Table 2–16. 	
February 2005 v1.2	Updated figure 2-12.	
November 2004 v1.1	Updated Table 2–19.	
June 2004 v1.0	Added document to the Cyclone II Device Handbook.	